

# WAGASCI ELECTRONICS USER GUIDE

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# Chapter 1

## WAGASCI electronics

In this chapter the DAQ electronics of the WAGASCI experiment is described in as much detail as possible. With this statement, I don't mean that I am going to write down again everything that there is to know about the WAGASCI electronics: if there is any source that contains some relevant piece of information, I am going to cite that reference and consider that content as covered.

### 1.1 Overview

The WAGASCI DAQ system electronics is composed of many different boards (Figure 1.1). All of them were developed at LLR (Laboratoire Leprince-Ringuet) in France. Please refer to the following articles for an introduction to every board of the system[8, 5]. Be warned that these articles and all the ones that follow through the chapter, describe the general features of the DAQ system but don't explain how to actually use it. Moreover they are somewhat redundant, so if you choose to read them all, be prepared to read the same things over and over again. I cannot blame the authors too much for this kind of "publication" spamming. If I were them, after so much effort to develop a new DAQ system (both hardware and software), I would like at least to get as many publications as possible out of it, too.

On the other hand this very documentation is meant more as a "User Guide", so, while referring to the said literature for the more general and technical remarks, I will only focus on practical usage scenarios and examples.

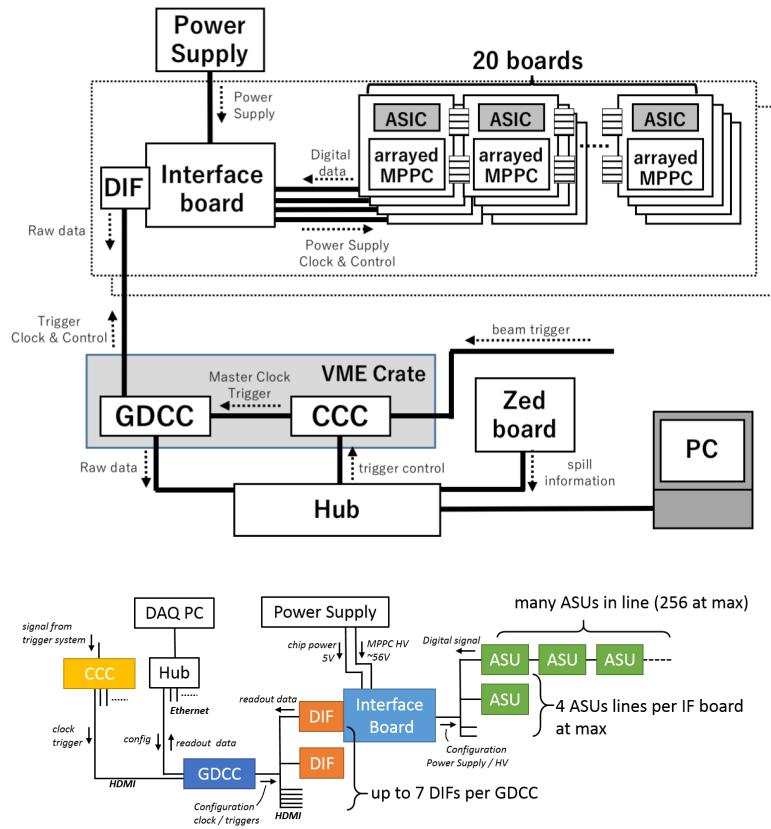


Figure 1.1: Schematics of the WAGASCI DAQ system electronics. These figure only shows the connections for a single DIF. The maximum theoretical number of ASUs for a single DIF is 4x256 but no more than 4x5 is needed for WAGASCI.

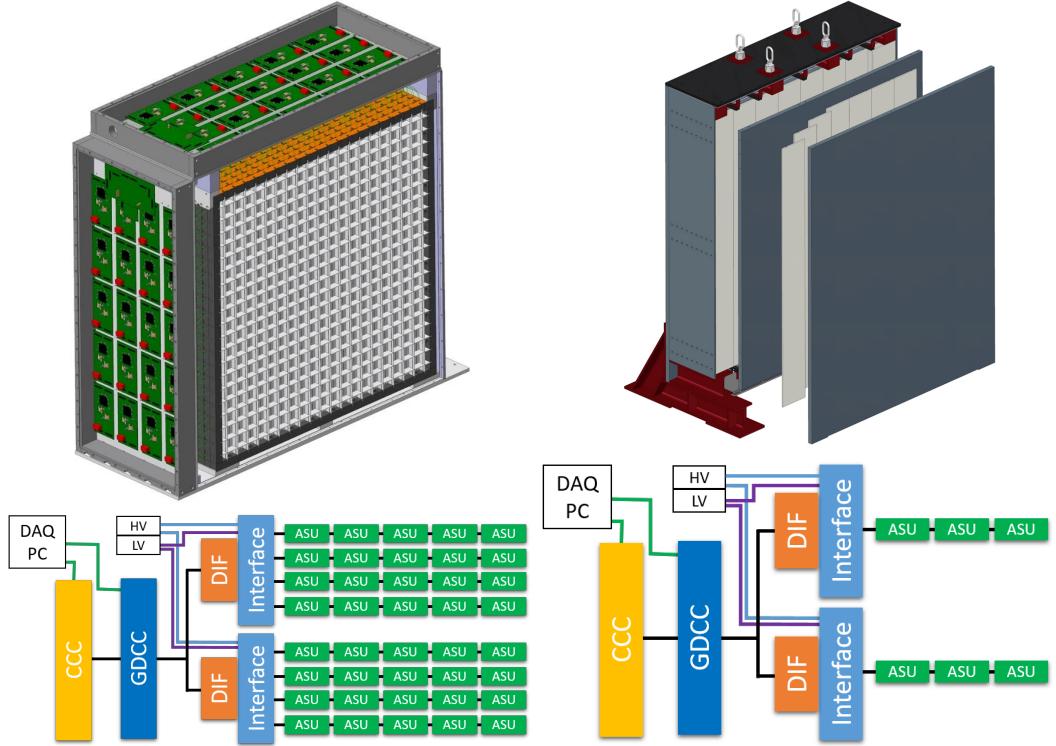


Figure 1.2: Schematics of WAGASCI boards and Figure 1.3: Schematics of SideMRD boards and connections for a single detector. For two detectors-connections for a single detector. For two detectors everything doubles but the GDCC, CCC and DAQ PC

### 1.1.1 List of boards, connectors and cables

In this section, I try to list some of the boards, connectors and cables for the WAGASCI experiment. I only focus on the parts that we may need to (re)-purchase in future. This is not meant to be a thorough list but more like a memo to my future self if we ever have to shop for spares or replacements.



Figure 1.4: Schematics of the WAGASCI housing connectors

To check if the connectors really match with the figure

Feedthrough connector	#	Remarks	Reference
HDMI	2	GDCC-IF	RS 909-3717
SHV (Safe High Voltage)	2	HV-IF	RS 212-7444
Binder 5 contacts	2	LV-IF	Binder 09-0115-80-05
Binder 6 contacts	2	JTAG for DIF firmware upgrade	Binder 09-0123-80-06
Binder 14 contacts	2	For DIF LED	Binder 09-0453-80-14

Table 1.1: Housing feedthrough connectors.

Purpose	Cables/Connectors	#	Remarks	Reference
<b>DIF data</b>	50cm HDMI	2	to DIF	Any cable is good
<b>IF LV</b>	50cm LV wire	2	to IF LV	Digi-Key A6305SL-100-ND
	MOLEX contacts	10	to IF LV	RS 670-6445
	MOLEX housing	2	to IF LV	RS 670-4174
<b>DIF flash</b>	JTAG housing	2	to DIF	RS 673-7626
	JTAG contacts	20	to DIF	RS 714-2404
<b>LED</b>	15 wires cable	2	Extra LED	3470/15C SL005
	ISDF housing	2	Extra LED	RS 180-0450
	ISDF contacts	28	Extra LED	RS 180-1564
<b>ASU</b>	10cm 50-pin flat cable	64	ASU-ASU	RS 901-1848
	22cm 50-pin flat cable	16	ASU-IF	RS 901-1857
<b>HV</b>	LEMO	2	to IF HV	RS 320-2568

Binder connectors are currently not on sale in Japan. They may appear again on sale on RS Japan in future.

Table 1.2: Cables and connectors for inside the housing.

Purpose	Cables/Connectors	#	Remarks	Reference
<b>DIF data</b>	?cm HDMI	2	to GDCC	Any cable is good

To check where the LED cable have to be connected

Continued on next page

Purpose	Cables/Connectors	#	Remarks	Reference
<b>IF LV</b>	Binder 5 contacts (plug)	2	to LV	<a href="#">Binder 99-5114-00-05</a>
	Crimping terminals	4	to LV PSU	<a href="#">RS 604-8389</a>
<b>DIF firmware</b>	Binder 6 contacts (plug)	2	to DIF	<a href="#">Binder 99-5122-00-06</a>
	JTAG cable's wires	2	to XILINX	<a href="#">0034302</a>
<b>LED</b>	Binder 14 contacts (plug)	2	to LED	<a href="#">Binder 99-5452-00-14</a>
<b>IF HV</b>	SHV connector female	2	to HV	<a href="#">RS 212-7438</a>
	BNC 50Ω	2	to HV PSU	<a href="#">RS 546-4853</a>
	Coaxial Cable	2	50 Ω	<a href="#">RS 222-8610</a>
	DSUB connector	2	to HV PSU	???

Table 1.3: Cables and connectors for outside the housing.

Cables/Connectors	#	Remarks	Reference
Flat cable (34 wires)	1	spill number (ECL signal)	???
Hirose connector (10 pins)	2	TTL input (on ZedBoard)	<a href="#">RS 896-0809</a>
8ch. LEMO - 10-pin flat cable	2	TTL signal (to Pmod connector)	???

To check the length of the HDMI cables and the model of the DSUB cable

Table 1.4: Cables for beam trigger and spill number processing.

Item	Remarks	Reference
Switch (Hub)	NETGEAR 16 Port Switch	<a href="#">JGS512 v2</a>
NIM crate	Large current type	<a href="#">RPN-005-153</a>
VME crate	special processing RPPV-2016W (without J2, rail positions changed)	???
Front-end DAQ PC	DAQ PC	<a href="#">Dell PowerEdge R330 Rack Server</a>

To check the references

Continued on next page

Item	Remarks	Reference
Back-end Slow Control PC	ANA PC	Dell PowerEdge R530 Rack Server

Table 1.5: Items on the WAGASCI rack.

To check the VME crate remarks meaning

Item	Remarks	Reference
PicoLog 1012	Water Level sensor probe	PicoLog 1012
TDK 200W 80V 2.5A	HV PSU	ZUP80-2.5
TDK 200W 6V 33A	LV PSU	ZUP6-33

Table 1.6: Slow Control Items.

Item	#	Remarks	Reference
DIF connector (housing)	2	8-contacts	RS 673-7626
DIF connector (contacts)	16		RS 714-2404
Xilinx USB cable	1	HW-USB-FLYLEADS-G	RS 697-3456
Binder 6 contacts	2	JTAG for DIF firmware upgrade	Binder 09-0123-80-06
Binder 6 contacts (plug)	1	to DIF	Binder 99-5122-00-06

Table 1.7: Cables and connectors for the DIF firware update.

### 1.1.2 References

The documentation about the WAGASCI electronics is relatively vast but randomly dispersed through the net. Here I am providing a compilation of all the available literature that I could find.

- Master Theses about the WAGASCI electronics and DAQ system: Chikuma Naruhiro [17], Tamura Riku [19].
- Articles about the WAGASCI electronics (but not directly referring to the WAGASCI experiment): [8, 5, 7].
- General articles about pre-amplifiers and amplifiers used for Physics measurements [12, 2, 14, 1] and everything about signal processing that you can find in the Knoll book [13]. This should be enough to get you started. Of course there is much more online about Physical applications of pre-amplifier and amplifiers.
- Articles and slide shows about the SPIROC characterization [4, 3, 6, 15, 18].
- SPIROC manuals and pin-out [10, 9, 16].

## 1.2 MPPC

This section is only a stub. It is only meant as a list of calibration parameters.

### 1.2.1 Gain Calibration

All gains are required to stay within 10%.

To write  
about cali-  
bration pro-  
cedure

### 1.2.2 Arrayed MPPC

- (SPIROC2D) PreAMP gain parameter = 49-50 (Fixed for each channel)
- HV bias voltage = 56.1V (Common for all channels)
- Breakdown voltage mean = 51.8V
- Over-voltage = about 3V
- 8-bit DAQ adjustment range = 0 to -2.5V (Bias voltage = 53.6-56.1V)
- Target gain = 40 ADC counts
- Pedestal = about 500 ADC counts
- High Gain range = up to about 300ADC = about 60 to 70 p.e.
- Low Gain range = HG x 10 => Up to 600 p.e

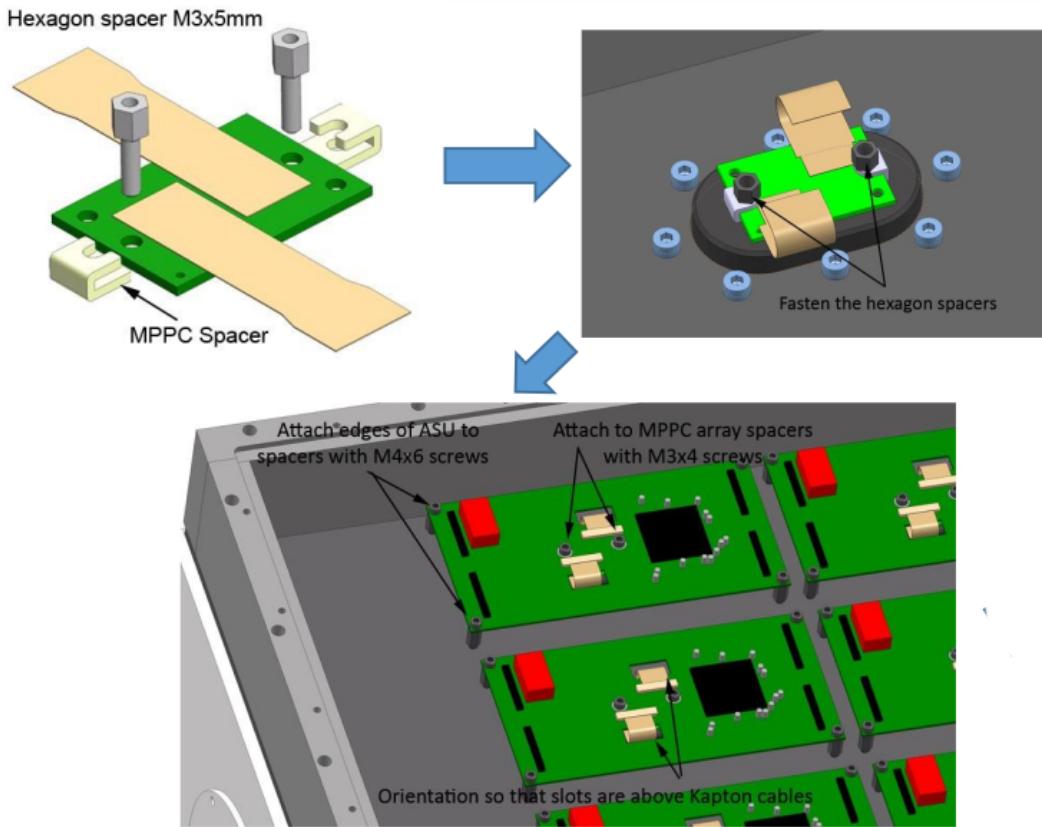


Figure 1.5: How to mount Arrayed MPPCs on the WAGASCI module.

### 1.3 SPIROC2D

The SPIROC2D chip can be considered as the heart of the WAGASCI DAQ system. It is directly connected to the MPPCs and plays the role of pre-amplifier, amplifier and digitalization of the raw signal. It is contained in an ASIC called [ASU](#) (Section 1.3.2). In Figure 1.1 it is indicated with the general term ASIC.

SPIROC is a dedicated very front-end chip developed originally for an ILC prototype hadronic Calorimeter with SiPM readout (CALICE experiment). It has been realized in  $0.35\mu\text{m}$  SiGe technology. It has been developed to match the requirements of large dynamic range, low noise, low consumption, high precision and large number of readout channels needed. The SPIROC version used for the WAGASCI DAQ is SPIROC2D.

The SPIROC ASIC that reads 36 SiPMs is an evolution of the FLC\_SiPM used in the CALICE experiment prototype. The first SPIROC prototype has been produced in June 2007 and packaged in a CQFP240 package. A second version, SPIROC2, was realized in June 2008 to accommodate a thinner TQFP208 package and fix a bug in the ADC.

SPIROC is an **auto-triggered** (it is possible to set a threshold value below which no data is acquired), **bi-gain** (there are two pre-amplifiers one with low gain for bigger signals and another with higher gain for smaller signals), **36-channel** ASIC which allows to measure on each channel the charge from one photoelectron to 2000 and the time with a 100ps accurate TDC (be warned

that accuracy and precision are two distinct concepts). An analog memory array (Switched Capacitor Array) with a depth of 16 for each is used to store the time information and the charge measurement. Refer to Wikipedia for more info about the SCA (this should be more than enough if you are an experimental physicist like me).

A 12-bit Wilkinson ADC has been embedded to digitize the analog memory contents (time and charge on 2 gains). The data are then stored in a 4 kilobytes RAM. A very complex digital part has been integrated to manage all these features and to transfer the data to the DAQ.

A small list of the most basic SPIROC properties:

- ASIC name: SPIROC (Silicon PM Integrated Read-Out Chip)
- Current available version: 2A,2B,2C,2D,2E
- Number of channel: 36
- Polarity of input signal: positive
- Detector read out: SiPM, MPPC, compliant with PM, MA-PM
- Max input signal: 2000 photoelectrons at minimum gain

### 1.3.1 Short description

Please read this section only after having read at least some of the references above otherwise it probably won't make much sense.

Each channel of SPIROC2 is made of:

- An 8-bit input DAC with a very low power of  $1\mu\text{W}/\text{channel}$  as it is not power pulsed. The DAC also has the particularity of being powered with 5V whereas the rest of the chip is powered with 3.5V. Think of this DAQ as a way to fine tune the High Voltage supplied to the MPPCs in a range from -4V to +4V. TO-CHECK the range. This tuning directly reflects on the gain of that particular channel. It is possible to control this value by tweaking the TO-DO
- A high gain and a low gain pre-amp in parallel on each input allow handling the large dynamic range. A gain adjustment over 6 bits common for the 64 channels has been integrated in SPIROC2. TO-CHECK it is not clear!
- The charge is measured on both gains by a “slow” shaper (an amplifier with pulse duration of 50–150ns) followed by an analogue memory (SCA) with a depth of 16 capacitors.
- The auto-trigger is taken on the high gain path with a high-gain fast shaper followed by a low offset discriminator. In other words the input signal is first processed by the high-gain pre-amp and then compared with a given threshold (that can be adjusted). If the signal is “over” the threshold the acquisition is triggered, otherwise the signal is ignored. By low offset I mean that (due to a hardware error) the threshold is not set on the main part of the pulse but on the lower part of the pulse as one can see in figure 1.6. This erroneous behavior has been fixed in the SPIROC2E version but it has been shown that it doesn't affect the measure so much as to require a replacement of all the chips.

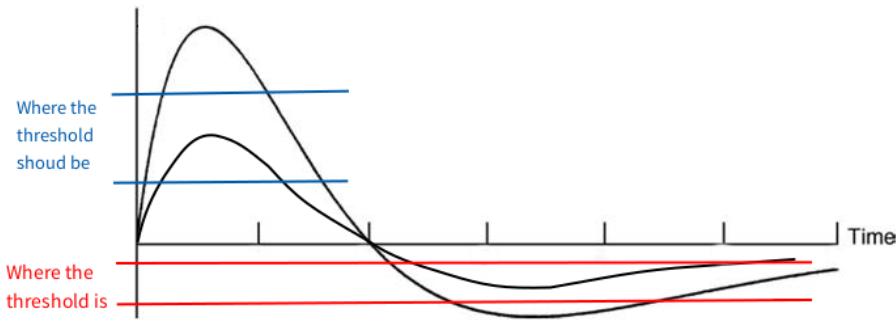


Figure 1.6: The threshold should be applied on the upper part of the signal and not on the lower. This figure shows two signals over the respective thresholds. The blue lines show where the threshold should be: in this case only signal ABOVE the threshold value trigger acquisition. The red lines show where the threshold actually is: in this case only signals BELOW the threshold value trigger acquisition.

The discriminator output is used to generate the hold-and-track on the 36 channels. The threshold is common to the 36 channels, given by a 10 bit DAC with a subsequent 4 bit fine tuning per channel.

- The discriminator output is also used to store the value of a 300ns ramp in a dedicated analogue memory to provide time information with an accuracy of 100 ps.
- A 12 bit Wilkinson ADC is used to digitize the data at the end of the acquisition period.

The digital part is complex as it must handle the SCA write and read pointers, the ADC conversion, the data storage in a RAM and the readout process.

The chip has been extensively tested by many groups. The first series of tests has been mostly devoted to characterizing the analog performance, which meets the design specifications.

### 1.3.2 ASU



Figure 1.7: Active Sensor Unit (ASU) board

Active Sensor Unit (ASU) board is the name of the PCB board containing the SPIROC2D chip. It is basically an adapter to connect the SPIROC chip to the MPPCs and to the rest of the DAQ system. The ASUs can be daisy-chained together until a maximum of 40 units (4 rows of 5 ASUs) for every DIF, as can be seen in Figure 1.8.

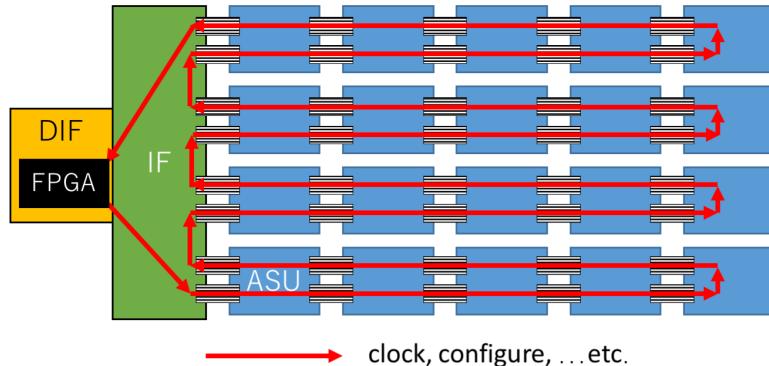


Figure 1.8: Schematic of ASU daisy chain

The jumpers of the last ASU of every row must be set as shown in Figures 1.9, 1.10 and 1.11 to reflect the signal back to the interface.

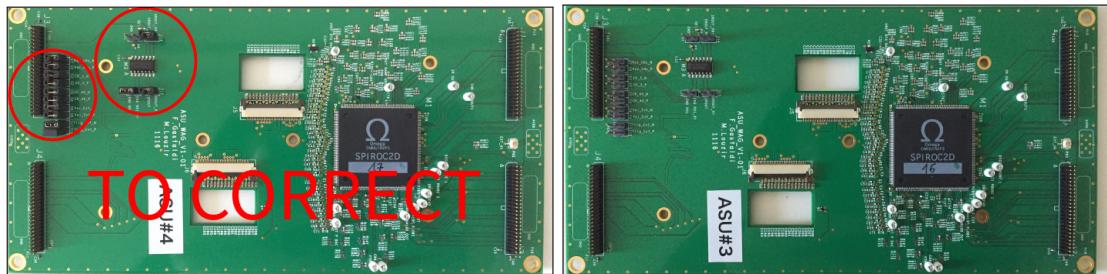


Figure 1.9: ASU with jumpers

Figure 1.10: ASU without jumpers

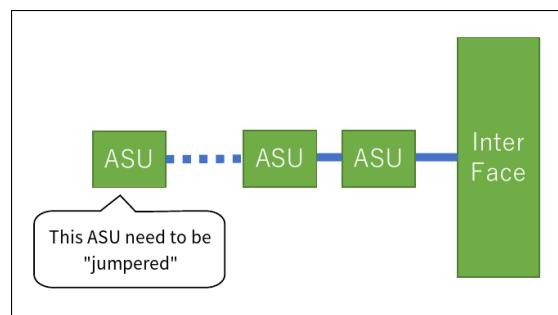


Figure 1.11: How to daisy chain and jumper the last ASU of the row.

## 1.4 Interface



Figure 1.12: Interface (before buffer addition)

This board has no important function by itself. It is just a sort of adapter to connect all the ASUs to the DIF, to route the High Voltage to the MPPCs (through the SPIROC2C chip) and to route the Low Voltage to the SPIROC2D chip itself and to the DIF. Despite being the most trivial board of the system it is the component that gave more problems in the past.

The connectors are quite fragile and I counted at least 5 boards broken when disconnecting some cables (including one by myself). In particular take extra care when connecting-disconnecting the DIF and the Low Voltage.

The High voltage must be connected to the only LEMO 00 female connector that can be seen on the right of the DIF in Figure 1.29. Where to connect the Low Voltage cable is shown in Figure 1.31 and in Section 1.4.4.

The Interface shown in Figure 1.12 is just a prototype (before the patch described in Section 1.4.3 is applied). The actual Interface board may look different.

#### 1.4.1 How to connect the Interface to the ASUs

Each interface can be connected to 4 ASU chains. Depending on how many chains are to be connected, the Interface jumpers must be set appropriately (see next section). Refer to Figures 1.13, 1.14 and 1.15 for a visual explanation of how to connect the Interface and the ASUs.

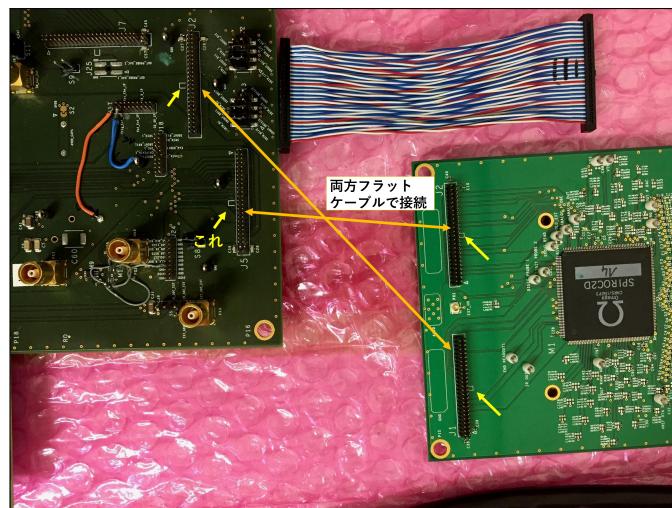


Figure 1.13: Interface (before buffer addition)



Figure 1.14: Pictures the flat cables that connect an ASU to its Interface

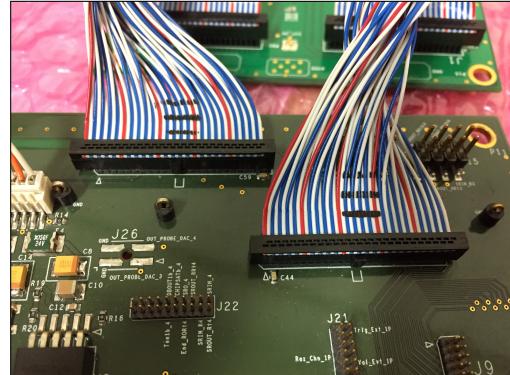


Figure 1.15: Close view of the connectors

As can be seen in Figure 1.14, depending on the relative position and orientation of the ASUs and Interface, it can happen that the cables cross. Notice also that the bump in the cable have to correspond to the silkscreen prints on the circuit. Refer to table 1.8 for the ASU-IF connections. The Jx mark is written on the PCB next to the relative connector, where x is the connector number.

Interface	ASU
J2	J1 (ASU1)
J5	J2 (ASU1)
J6	J1 (ASU2)
J7	J2 (ASU2)
J8	J1 (ASU3)
J9	J2 (ASU3)
J10	J1 (ASU4)
J11	J2 (ASU4)

Table 1.8: ASU - Interface connections

#### 1.4.2 How to set the jumpers on the Interface

Each interface can be connected to 4 ASU chains. Depending on how many chains are to be connected, the Interface jumpers must be set appropriately. The following four figures (1.16, 1.17, 1.18, 1.19) explain in detail which jumpers have to be set. Refer to table 1.9 for a summary of the pinout.

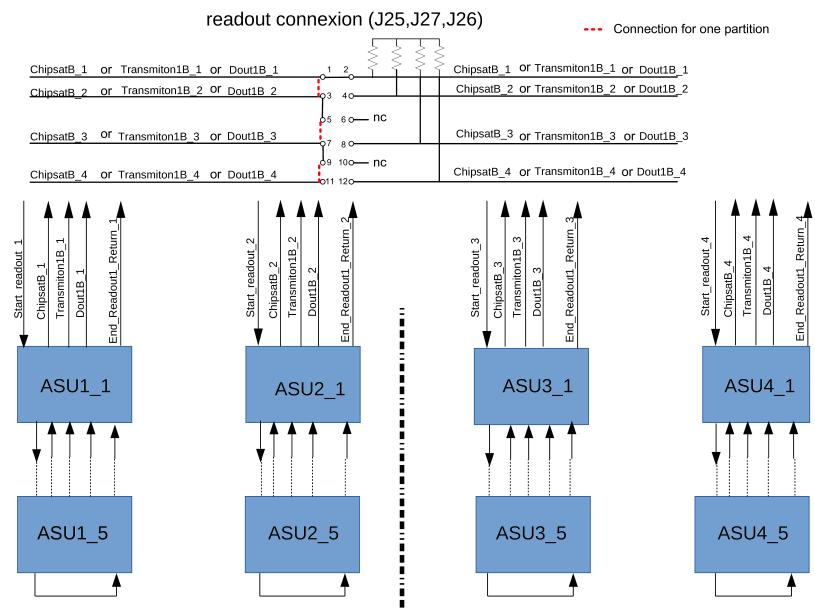


Figure 1.16

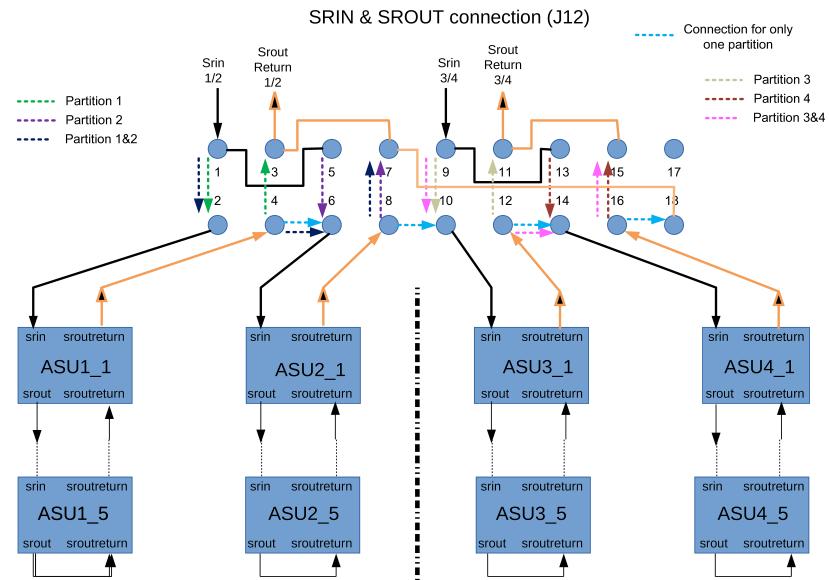


Figure 1.17

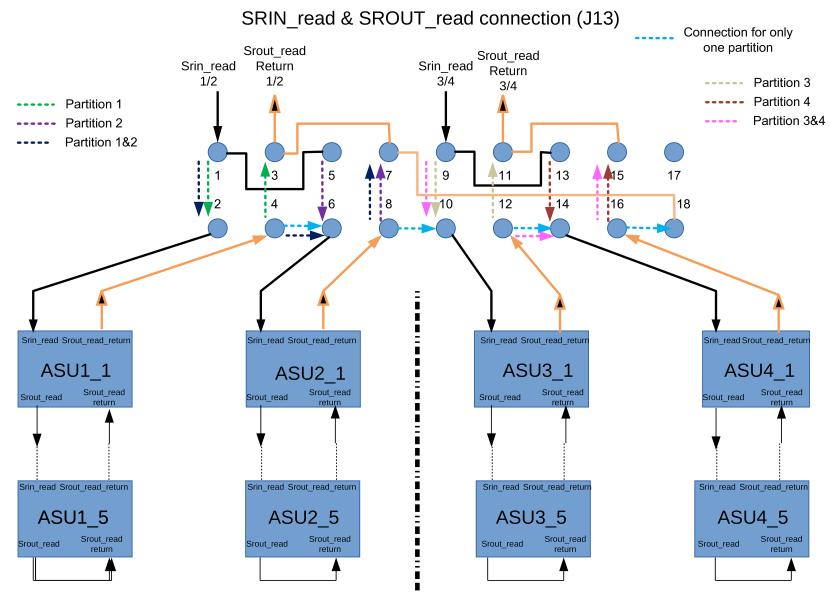


Figure 1.18

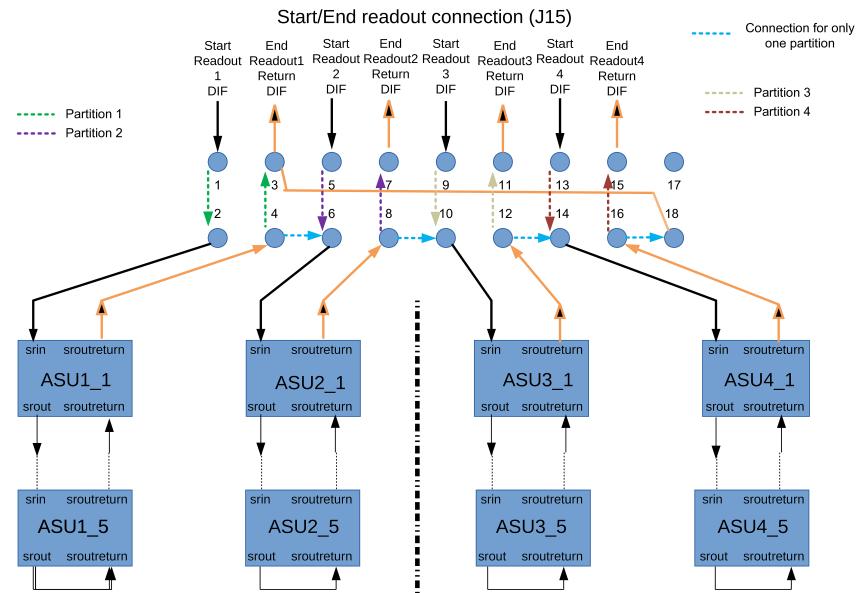


Figure 1.19

	<b>1 Chain (J2J5)</b>	<b>2 Chains (J2J5 and J6J7)</b>	<b>4 Chains</b>
<b>J12</b>	1-2,3-4	1-2,4-6,7-8	1-2,4-6,8-10,12-14,16-18
<b>J13</b>	1-2,3-4	1-2,4-6,7-8	1-2,4-6,8-10,12-14,16-18
<b>J15</b>	1-2,3-4	1-2,4-6,8-18	1-2,4-6,8-10,12-14,16-18
<b>J25</b>	no jumpers	1-3	1-3,5-7,9-11
<b>J26</b>	no jumpers	1-3	1-3,5-7,9-11
<b>J27</b>	no jumpers	1-3	1-3,5-7,9-11

Table 1.9: Interface jumpers. The dash '-' symbol indicates a direct connection of only two pins. So for example by 8-18 I mean connect pin 8 to pin 18 and NOT connect pin 8 to pin 9 to pin 10 to ... to pin 18. The pin numbers are not written on the interface. Until now I have no idea of how to determine the pin numbers but to look at already jumper-ed Interfaces or from the following Figure 1.20.

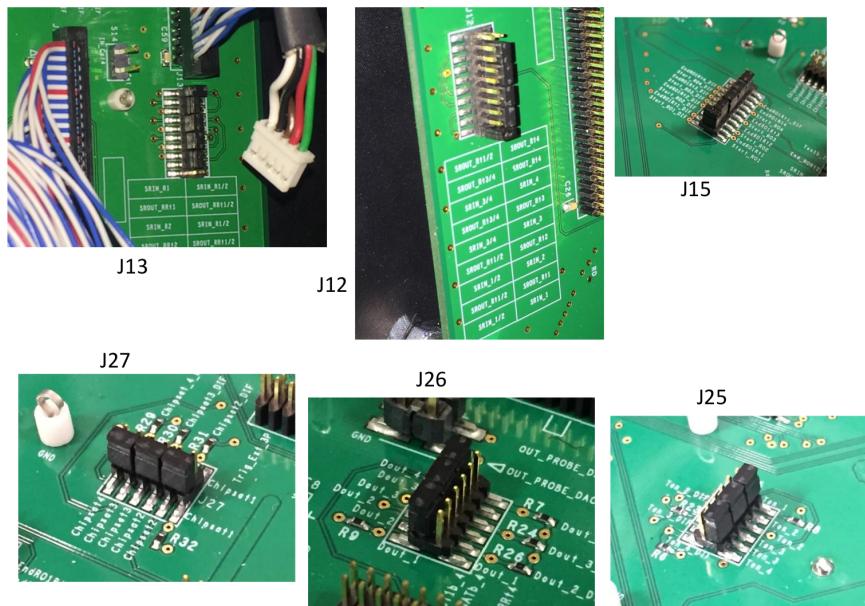


Figure 1.20: Interface jumpers setup for 4 (all) ASU chains

### 1.4.3 How to patch the interface

As can be read in Tamura Riku's thesis (after correcting some typos):

*[...] in order to check the correct operation of the full setup, the daisy chain configuration is firstly tested. The test is done by increasing the number of daisy-chained ASU boards one by one. Up to about 10 boards, the daisy chain is correctly configured but at around 10 boards the configuration starts to fail. After several tests with different configurations, it appeared that this is due to the attenuation and reflection of the bunch crossing clock (BCID) when it travels through*

*the chain: the signals, including the bunch crossing clock, are serially transported through the daisy chain so the length that they need to travel depends on the number of connected ASU boards. The total capacitance of the daisy chain depends on the number of connected ASU boards, too. This creates a mismatch of impedance between the endpoints and some DAQ signals are badly affected. In practice most of the DAQ signals are not so affected but it seems that the bunch crossing clock is strongly affected. The whole DAQ acquisition phase is synchronized to the bunch crossing clock so this is a very critical issue.*

*Fortunately, this problem can be fixed by “patching” the bunch crossing clock line. To prevent the attenuation of bunch crossing clock and match the impedance a 4ch buffer, CDCLVC1104[11], is applied to the bunch crossing clock line as shown in Figure TO-DO. This buffer is a highly performing and fast responding one. The delay it adds to the BCID is of 0.8-2ns, which is less than 1% of the period of bunch crossing clock, so the effect on the timing measurement due to the BCID is negligible. This patch is tested to work fine and the daisy chain is configured correctly even with the full setup (20 ASUs). [...]*

Long story short, we have to patch every interface with that chip if we want to daisy-chain more than 10 ASUs. Just to be on the safe side, all the interface boards, even if connected to less than 10 ASUs, were fixed with the following procedure.

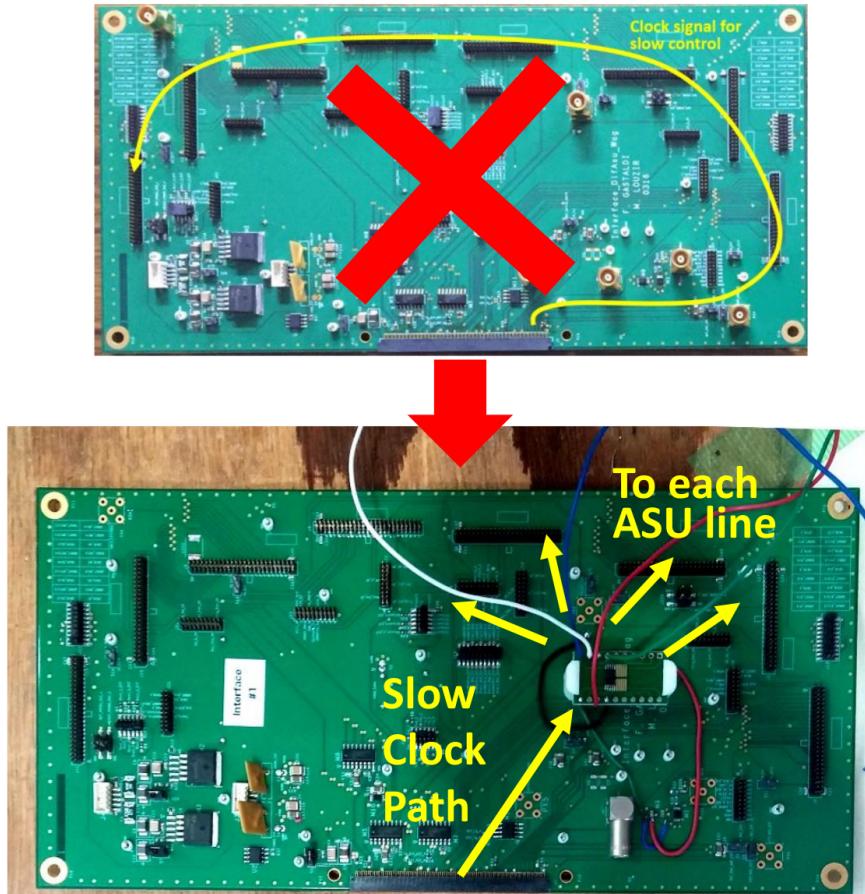


Figure 1.21: Cartoonist impression of the reason why we need to patch the Interface with a buffer chip.

Here I will show how to concretely fix the interface. I came to know about this procedure by reading two pdf files that were sent to YNU from I don't know where. I must admit that until now they hold the record for being the most unintelligible piece of paper that I have ever read. No matter how much I strove, I think that I could never write in such a cumbersome manner even if I want to. Anyway ...

1. First solder the CDCLVC1104 chip on the base and glue it on the board (any empty space on the interface is good) as shown in Figure 1.22. You can use a different support (the white piece of plastic) and base (the small PCB with 10 holes on each side) if you want.

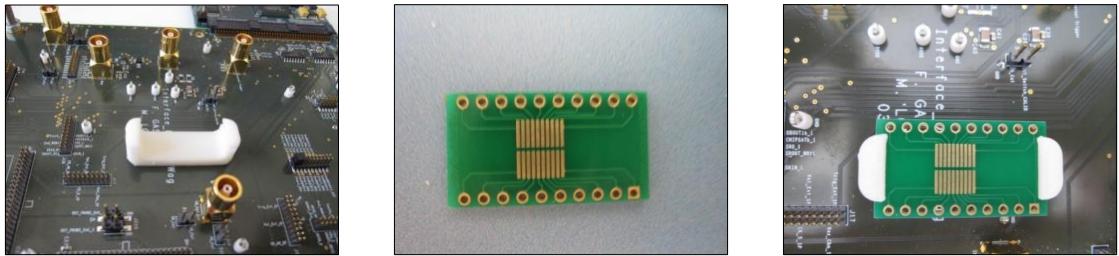


Figure 1.22: PCB Base (in the middle) glued to the interface board using a plastic support (on the left). The buffer chip must be soldered on that base (not shown in the pictures, yet). You can solder the buffer chip in any position on the base as long as it is soldered properly.

2. Then take a 50 pins flat cable (that you are then going to connect to the J2 connector). Cut in the middle the wires number 13, 49 and 50 (SR\_CK\_BUF, TRIG\_EXT\_N and TRIG\_EXT\_P respectively). Refer to Figure 1.23 for the flat cable pin-out. Strip the “ASU end” of these wires. By ASU end I mean the end that is not to be connected to the interface but to the ASU. If needed do the same for the other flat cables coming out the connectors J6, J8 and J10.

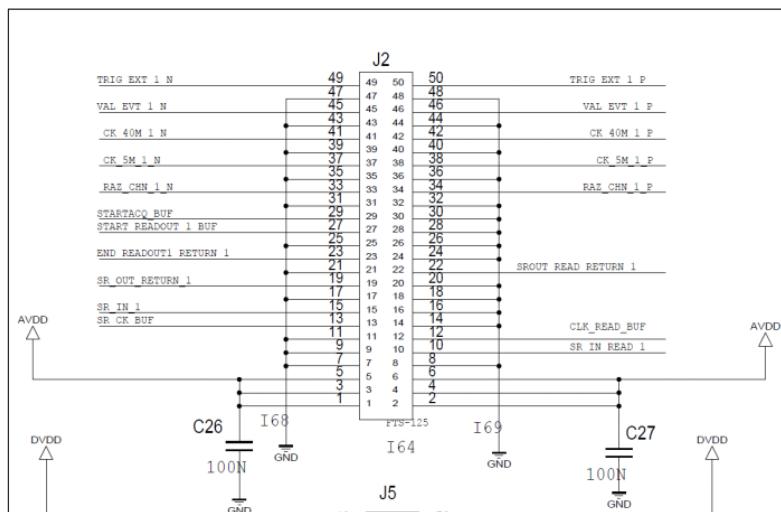


Figure 1.23: J2 connector pin-out

- ### 3. Desolder the M9 chip

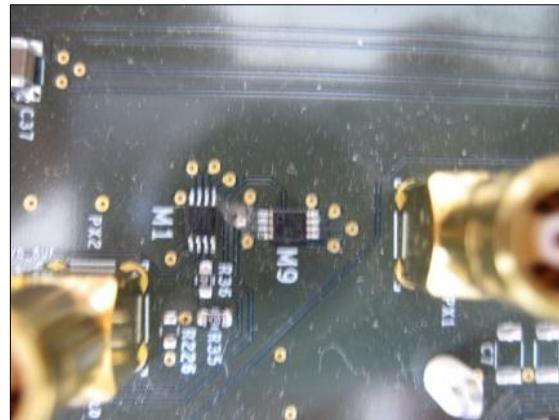


Figure 1.24: CDCLVC1104 chip pin-out

4. Referring to Figures 1.26 and 1.25, connect with some wires the pins in this way:

color	CDCLVC1104 pin	Interface pin
brown	1 CLKIN	SR_clk
red	6 VDD	(refer to picture)
black	4 ground	Interface ground

Table 1.10: Fast command packet format

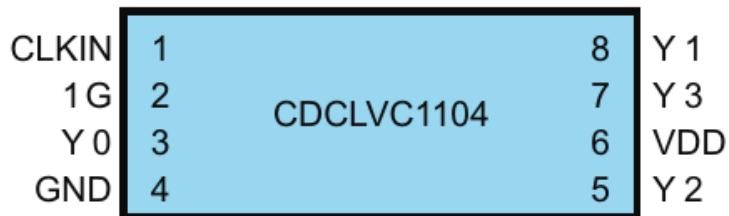


Figure 1.25: CDCLVC1104 chip pin-out

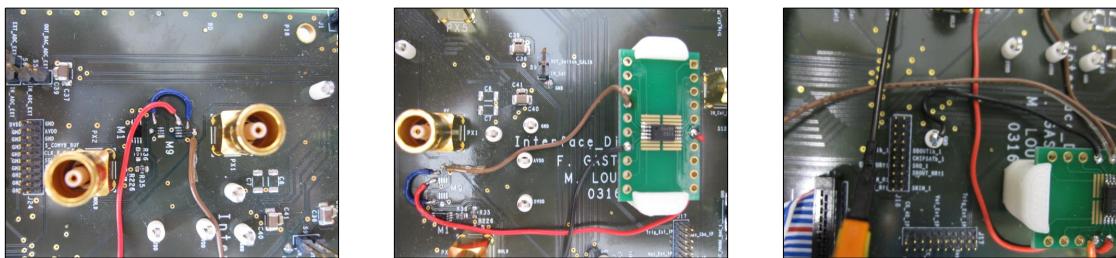


Figure 1.26: Interface connections

I am sorry but in the document that I was given there is no schematics regarding the holes around the M9 chip, so we had to solder referring only to the attached pictures.

5. (Optional but recommended) Solder a capacitor of 100nf to decouple power and ground between the pins 6 VDD and 4 GRD of the buffer. It is not shown in the pictures.
6. Now connect the interface holes around the M9 chip as shown in Figures 1.26 (blue cable). In the document I was given those are called pin number 1 and 7. Anyway, as I said, without the schematics those numbers are meaningless. Sometimes I wonder if Physicists are really so smart as they think to be.
7. Pins 3,5,7,8 of the buffer chip represent the output of the buffer. Connect each pin to the wire number 13 of the flat cables coming off J2, J6, J8 and J10. The order is not relevant. Of course, in the case of the SideMRD, only one connection is needed (for example J2). Refer to Figure 1.27 for a visual explanation.

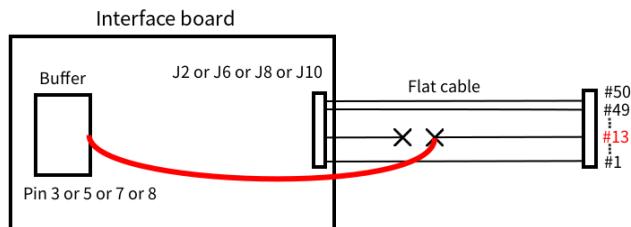


Figure 1.27: How to connect the #13 wire to the buffer.

8. Connect wire number 50 of the flat cable (it is white in our case) to any ground pin on the interface board. You have to connect the “ASU end” of the wire to ground in a similar way as shown in Figure 1.28 for the case of cable 13.

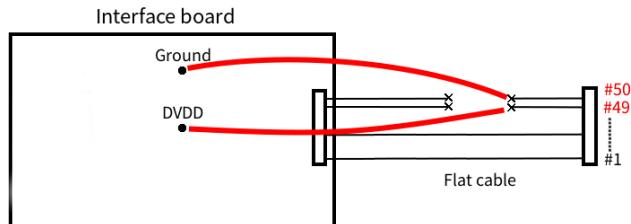


Figure 1.28: How to connect the #49 and #50 wires to the DVDD and Ground pins.

9. Connect wire number 49 of the flat cable (it is blue in our case) to the DVDD pin on the interface board. The DVDD pin is located near the M9 chip that you just desoldered. You have to connect the “ASU end” of the wire to the DVDD pin in a similar way as shown in Figure 1.28 for the case of cable 13.
10. The final result should look more or less like Figure 1.29.

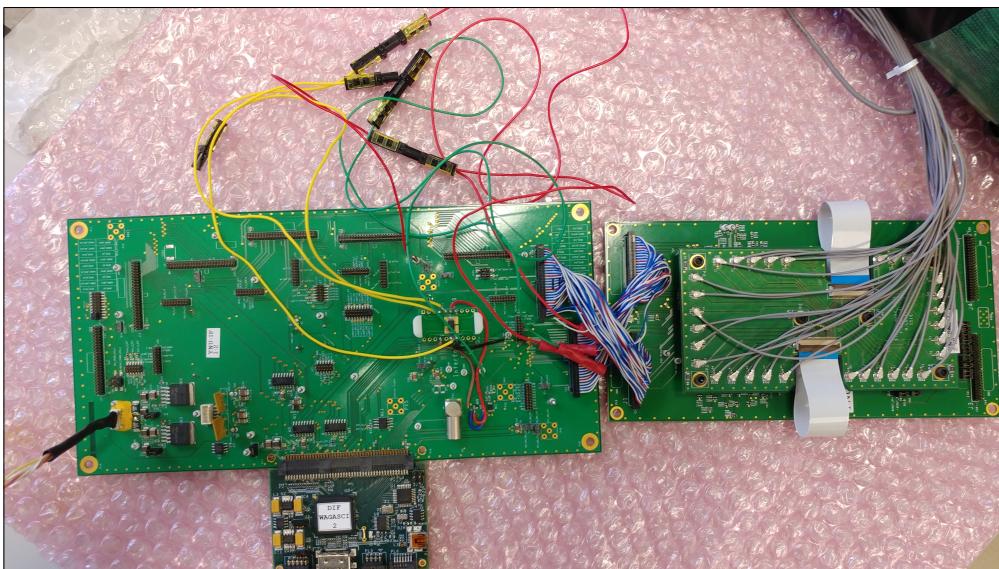


Figure 1.29: Final result. The ground wire coming from wire 50 of the flat cable is red (sorry for the ambiguity). The green wire is coming off from wire number 49 and is connected to the DVD pin on the Interface. In total there are three yellow output wires coming off the buffer chip but only one is actually used.

#### 1.4.4 How to make a Low Voltage cable

For bench-testing purposes you may need to make your own Low Voltage cable to power the Interface and all the other boards connected to it.

The Low Voltage cable must be connected to the interface using a 5 pins connector to a vertical wire-to-board socket that looks like this:

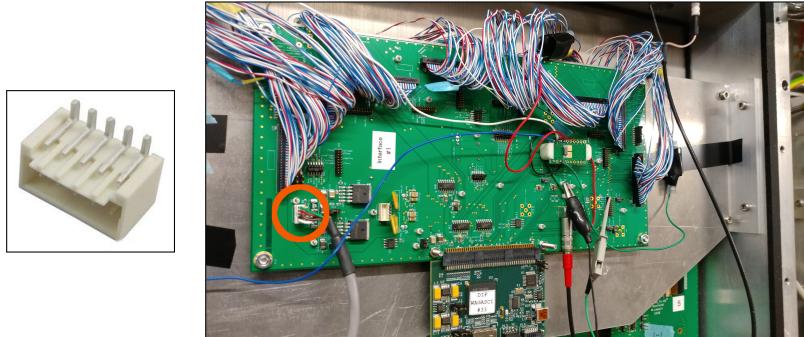


Figure 1.30: Vertical wire-to-board 5-pins socket on the Interface board for the Low Voltage connection

To make the cable just buy a male connector (TO-DO insert link) and connect the pins following the pin-out of Figure 1.31.

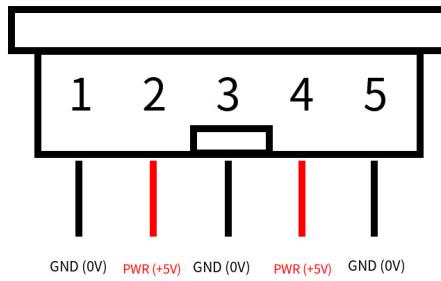


Figure 1.31: Vertical wire-to-board 5-pins socket on the Interface board for the Low Voltage connection

The ground wires can be grouped together in a single wire. The 5V wires can be grouped together in a single wire, too. The resulting 2 wires end of the cable can be terminated as you like and then connected to a 5V power supply. The power supply should be able to generate at least TO-DO Amperes of current.

## 1.5 DIF

I have not much to say about the Detector InterFace (DIF) board. It converts the signal from the ASUs into HDMI and sends it to the GDCC. It also controls the synchronization and reset of the slow clock (BCID). Until present there were many issues related to the slow-clock reset and synchronization, all of which have been luckily solved by a DIF firmware upgrade. To know more about the DIF please contact Matsushita Kouhei (Tokyo University): he was the one that tested the new firmware. To flash the updated firmware refer to Section TO-DO

Remember to note down the port number (Figure 1.32) on the GDCC side that you connect each DIF to, because you will have to insert that number in the configuration file TO-DO.

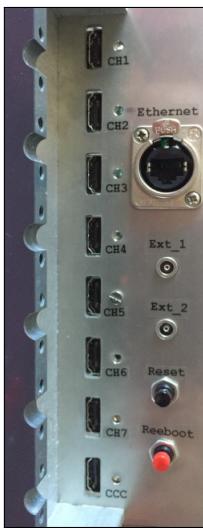


Figure 1.32:  
GDCC front view



Figure 1.33: Detector InterFace (DIF)

### 1.5.1 DIF Firmware upgrade

Refer to table 1.7 for the list of needed parts.

<b>Connector on DIF</b>	<b>1</b>	<b>2</b>	<b>3</b>	4	5	<b>6</b>	7	<b>8</b>	NC
<b>Connector on Housing</b>	<b>1</b>	<b>2</b>	<b>3</b>		NC	NC	<b>4</b>	<b>5</b>	NC
<b>Xilinx USB cable</b>	<b>TCK</b> (Yellow)	<b>GND</b> (Black)	<b>TMS</b> (Green)	NC	NC	<b>TDI</b> (White)	<b>TDO</b> (Purple)	<b>VREF</b> (Red)	NC (Gray)

Table 1.11: Pinout for the TDK-Lambda ZUP6-33 LV PSU

## 1.6 GDCC

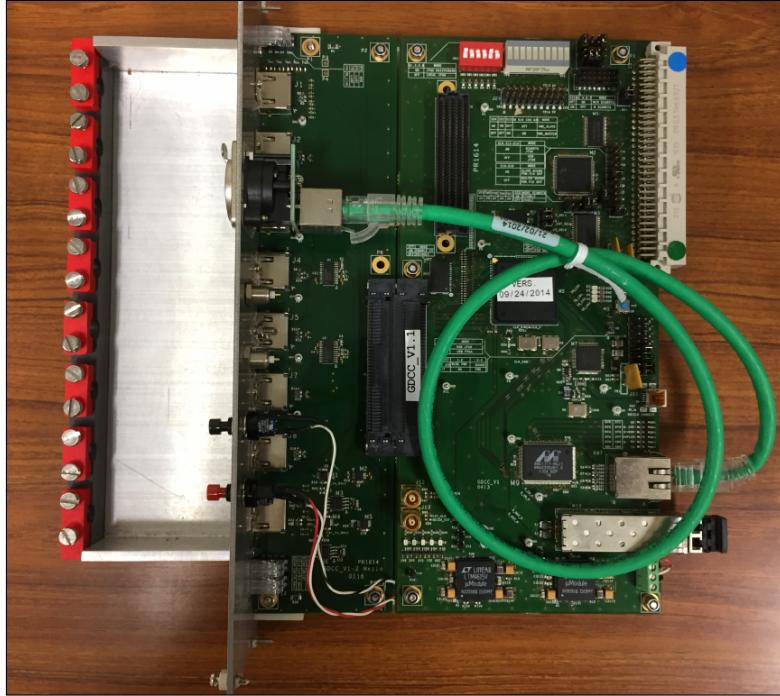


Figure 1.34: Gigabit Data Concentrator Card (GDCC) or Clock and Control Card (CCC)

I have not much to add in addition to what is already in the literature quoted in Section 1.1. This is the board that I know the least about, just because, fortunately, it just works and has never given any problem so far.

Please refer to the literature [7] or Appendix 2.2 if you want/need to know more about the GDCC.

The communication between the PC and GDCC is built on standard Ethernet. Communication to and from it is done via RAW Ethernet packets. This is why it doesn't need an IP address. This way communication between the DAQ PC and the GDCC can be faster than if they traveled through the IP layer but the GDCC must necessarily be located on the same physical LAN network as the DAQ PC.

The GDCC communicates with the ZedBoard using raw Ethernet packets. This connection is through "Normal GDCC packets": **0x0810** (Appendix 2.2).

### 1.6.1 How to make a power supply cable

The GDCC is build in the standard VME layout. It is meant to be plugged into a VME crate slot for power and mechanical stability. As far as I know, communication with the VME crate is hardware-ready but not implemented in software yet.

In case you don't have a VME crate at hand you can easily fabricate a specific power adapter to power up the GDCC and CCC with a standard Power Supply Unit. The nominal voltage is DC +5V. The PSU must be able to supply at least 5A of DC current.

For this, you need to find or buy

- 2 VME female connectors (96 way 2.54mm pitch). One for the GDCC and another for the CCC (RS reference number: [RS 470-443](#)).
- A breadboard to solder the connectors and the cables onto (RS reference number in Europe [RS 457-0755](#), RS reference number in Japan [RS 664-7876](#)) (single side Matrix board, 2.54 pitch). You need only one boards that you can cut in 2 parts, one for each adapter.
- Black and red cable unipolar cable for connections.
- Two connectors to connect to the Power Supply (the connector type depends on your Power Supply and your “taste”).

In the following I will show how to concretely make the said cable using a hot air station and soldering iron. You don't necessarily need a hot air station and you can get the same result with only a soldering iron and a bit of patience. The following pictures refer to two cables made with slightly different techniques, so some minor details can differ between the pictures.

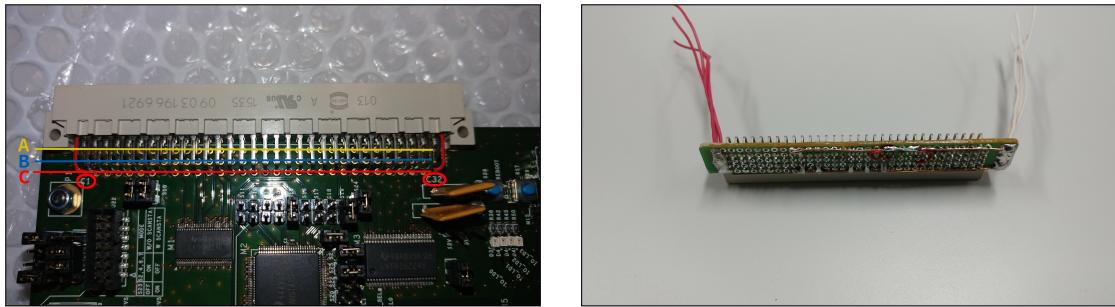
1. First cut the breadboard in the desired shape. As long as the cut breadboard doesn't hinder the two VME connectors from fitting one into the other, any shape is fine.
2. Then apply the solder paste evenly on the breadboard surface and insert the female connector. I have used two copper wires for the ground connections, but any other solution to make the connections is fine.



3. Solder all the pins using the hot air station (I recommend a air temperature of 370 degrees Celsius)



4. Solder the pins A32, B32, C32 together and connect these one to a red cable that you will then use for the 5V voltage. Then solder the pins A9, A11, A15, A17, A19, B20, B23, C9 together and connect these ones to a black cable that you will then use for the ground. To identify these pins you have first to identify the rows (A,B,C) and columns (1,2,...,31,32) of your connector. As explained before, you have to use a standard 3 rows, 92 pins VME female connector. This connector must have three rows labeled A, B and C and 32 pins for each row labeled 1,2,...,31,32, for a total of 96 pins. Don't look at whatever may be written on the adapter itself or on the internet because it might be different from the GDCC or CCC specifications (as happened to me). Just take a look at the GDCC and in particular at the silkscreen near the VME connector. As shown in the next picture, look for the C1 and C32 labels next to the respective pins. In the picture is also shown how to identify the A, B and C rows.



Then solder two long-ish wires for connecting the +5V and ground to a power supply and you cables are ready.



## 1.7 CCC

Clock and Control Card (CCC). It is used to process the beam trigger signal (Section 1.12), to create the spill flag variable, TO DO...

To communicate with the PC it uses the SiTCP hardware and protocol [20] with a fixed IP address of [192.168.10.2](http://192.168.10.2).

### 1.7.1 How to convert a GDCC into a CCC

Do you know how the Orcs first came into being? They were elves once, taken by the dark powers. Tortured and mutilated: a ruined and terrible form of life.

---

The Lords of the Rings

All the CCC boards are produced as GDCC and then converted in CCC by flashing a new firmware and slightly modifying the printed board. The modification is not so complex and with a minimum effort can be done by hand if one has the right tools.

To flash the firmware you need a Xilinx programmer like this: TO-DO

Once the firmware has been flashed it is time to modify the printed circuit. You only need to short the R28 and R29 resistors by inserting two  $0\Omega$  resistor in the appropriate pins.

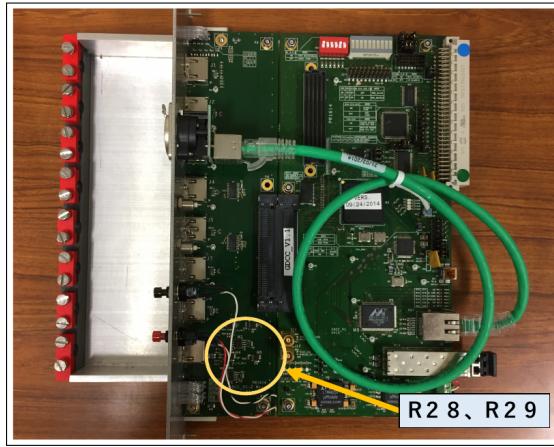


Figure 1.35: The position of the R28 and R29 resistors on the board.



GDCC(ショート前)



CCC(ショート後)

You can solder the resistors with a traditional solder iron or with a hot air gun. In any case you need at least two  $0\Omega$  resistors of size 1608 ( $1.6 \text{ mm} \times 0.8 \text{ mm}$ ). You can find them on the Japanese RS web-shop under the RS reference number “631-5667”. The full description is:

- KOA 厚膜チップ抵抗器, ジャンパーチップ抵抗器, 1608 サイズ,  $0\Omega$ ,  $\pm 0$   
RS品番 631-5667 メーカー型番 RK73Z1JTTD メーカー/ブランド名 KOA
- KOA thick-film resistor, jumper-chip resistor, size 1608,  $0\Omega$ ,  $\pm 0$   
RS number 631-5667 maker number RK73Z1JTTD maker/brand KOA

Anyway, the maker is not important as long as the value and size are correct. You can solder the resistor in at least two ways. One is with a soldering conical tip

- iron soldering you will also need:
  - solder (remember that lead is poisonous for all life forms including you)
  - tweezers ([monotaro number TSP-26](#))
  - flux ([monotaro number FS20001](#))
  - flux remover ([monotaro number BS-W20B](#))
- hot air gun soldering ([monotaro number FR810B-81](#)) you will also need:
  - solder paste (it already contains flux) ([monotaro number SMXB05](#))

- tweezers
- flux remover
- heat resistant tape ([monotaro number 15](#))

## 1.8 Low and High Voltage PS

### 1.8.1 TDK-Lambda ZUP6-33

Signal	GND	5.0V	GND	5.0V	GND
Molex on IF	1	2	3	4	5
Feed-through connector	1	2	3	4	5
Terminal on LV PSU	2	1	2	1	2

Table 1.12: Pinout for the TDK-Lambda ZUP6-33 LV PSU

### 1.8.2 HV PSU: TDK-Lambda ZUP80-2.5

	LEMO	SHV	DSUB
Signal	Central conductor	Pin	1
NC			2
GND	Outer shield	GND Lug Terminal	3

Table 1.13: Pinout for the TDK-Lambda ZUP80-2.5 LV PSU

### 1.8.3 HV PSU: Keithley 2400 SourceMeter

From the Keithley 2400 SourceMeter manual: *The Keithley 2400 SourceMeter combines a precise, low-noise, highly stable DC power supply with a low-noise, highly repeatable, high-impedance multimeter.*

I used this device at Yokohama National University as a High Voltage source for my tests. This section describes how to operate this instrument from a personal computer. Why go through the hassle of operating the Keithley from remote, if every operation can be also performed directly from the detector front panel? you may ask ... The fact is that, back then, I was still in the process of learning the Pyrame framework and I thought that writing the Pyrame interface for this instrument could be a good chance to test my comprehension of the Pyrame code. Anyway, you may skip this section if you don't own a Keithley 2400 or you are not interested in remotely operating it.

#### GPIB or RS-232?

You can connect the Keithley 2400 to a PC in two ways, each one with pros and cons. One way is by using the GPIB port and the other is by using the RS232 port.



Figure 1.36: The Keithley 2400 SourceMeter rear panel.

The General Purpose Interface Bus (GPIB but also called IEEE-488) is a short-range bus specification. Newer standards have largely replaced GPIB for computer use, but it still sees some use in the test equipment field. There are GPIB drivers for linux but they are not usually included in most distributions repositories, so you may have to compile them yourself. Since the WAGASCI DAQ runs on Linux I am not considering here Windows and Apple. For example, you can find a binary package for CentOS 7 ready to install but, in the case of Ubuntu, you have to compile it from source yourself.

To physically connect the instrument you have three options: a GPIB-to-USB adapter, a GPIB-to-Ethernet adapter or a PCI-GPIB board. I have personally tested only the GPIB-to-USB adapter case. The main problem with GPIB is that in any case, it is very expensive. The average price for any of those adapters is around 200\$ or 20000¥ on Amazon (probably much more on specialized sites).

- GPIB pros
  - You don't need to worry about the cable pinout
  - Adapters and cables are quite standardized so every cable and adapter will work just fine.
- GPIB cons
  - You need an adapter or a PCI-GPIB card
  - It is very expensive (both cables and adapters)
  - It requires you to install or compile specialized drivers
  - If you use a GPIB-to-USB adapter you are limited to 3 meters for the length of the USB cable

In the case of RS-232, only a simple serial cable with DB-9 connectors is needed.

- RS-232 pros
  - It doesn't require a specialized adapter (or a very cheap one) since virtually any Desktop motherboard already have a serial port (called sometimes COM port).

- Cables and adapters are quite cheap. In the case of a Desktop PC you can get by with very little money (20\$ or 2000¥).
- It doesn't required specialized drivers
- RS-232 cons
  - Choosing the right cable and adapter is difficult because there are so many different types of RS-232 cables.
  - You may need to refer to your motherboard and to the Keithley serial port pinout schematics to understand which is the right cable/adapter or to fix the adapter pinout if you bought the wrong one (like me).

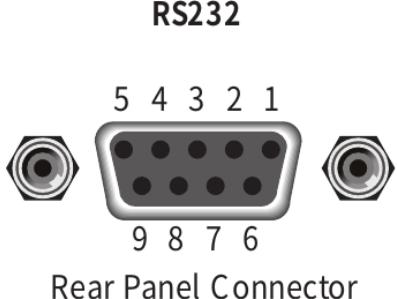
If you chose the GPIB option, you can go straight to section TO-DO to learn how to configure and use it in the Pyrame framework.

If you chose the RS-232 option in the next subsection I will explain how to chose the right cable and adapter and test if the pinout is correct.

### RS-232 connection and pinout

The Keithley RS-232 serial port is connected to the serial port of a computer using a straight-through RS-232 cable terminated with DB-9 connectors. Do not use a null modem cable. The serial port uses the transmit (TXD), receive (RXD), and signal ground (GND) lines of the RS-232 standard. Figure 1.37 shows the rear panel connector for the RS-232 interface and the pinout for the connector.

**RS-232 interface connector**



**RS-232 connector pinout**

Pin number	Description
1	Not used
2	TXD, transmit data
3	RXD, receive data
4	Not used
5	GND, signal ground
6	Not used
7	RTS, ready to send
8	CTS, clear to send
9	Not used

NOTE: CTA and RTS are tied together.

Figure 1.37

Most desktop motherboards have a serial port (usually called COM) port like shown in Figure 1.38 with the relative adapter (usually to be bought separately).

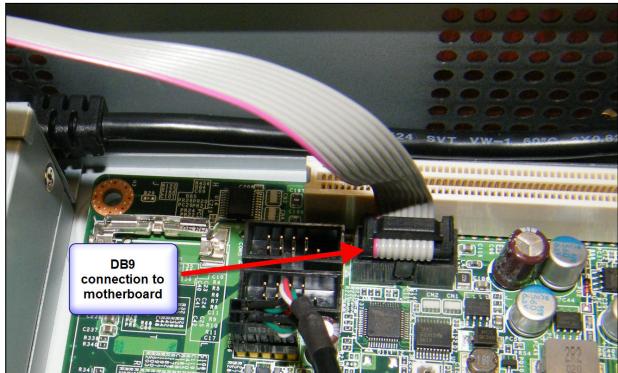


Figure 1.38: Serial port (COM port) on a motherboard with an adapter attached.

Refer to your motherboard manual for the correct pinout of the COM port. I made the mistake of buying the wrong adapter so I had to change the wires order. For example the motherboard that I used here is a ASUS PRIME H270 PRO and, according to the manual, the COM port pinout is shown in Figure 1.39

#### Serial port connector (10-1 pin COM)

This connector is for a serial (COM) port. Connect the serial port module cable to this connector, then install the module to a slot opening at the back of the system chassis.

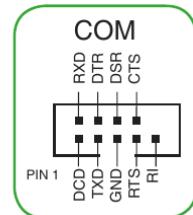


Figure 1.39: ASUS PRIME H270 PRO motherboard COM port pinout. It may be different in your case!!!

Notice that the pin TXD (Transmit Data) on the PC side (Figure 1.39) correspond the pin RXD (Receive Data) on the Keithley side (Figure 1.37) and vice versa. This is simply because the data transmitted by the PC is received by the instrument and vice versa. Same is for the RTS and CTS pins. Figure 1.40 shows what is the difference between the PC and device pinouts. Usually you only have to worry about the PC side.

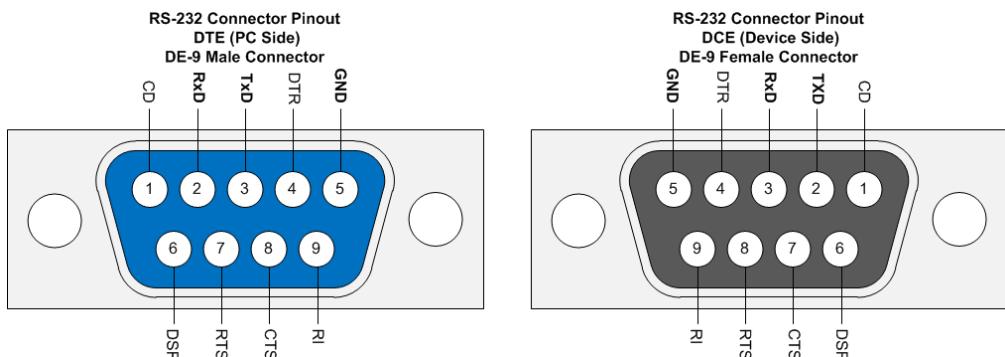


Figure 1.40: RS-232 DE-9 Connector Pinouts

I am afraid that, in any case, a certain degree of preemptive research is unavoidable to determine which are the best cable and adapter. If you are a WAGASCI collaborator and you are not confident in your choice, feel free to contact me.

### Serial cable loopback test

To test if the RS-232 adapter and cable are working OK, you can do a simple loopback test. A loopback test is a simple test where you short the transmit and receive pins of your cable or adapter (Figure 1.41) and try to simultaneously send and receive some random string over the cable. Since those pins are shorted the sent string is reflected back and received.

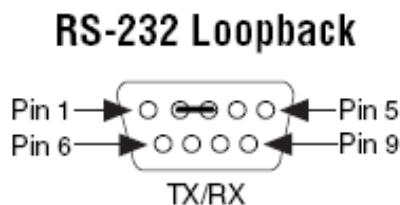


Figure 1.41: RS-232 loopback test: pins to short. You can use a simple jumper to short the pins.

Then open a two terminal on the PC and in one write:

---

```
sudo stty -F /dev/ttys0 9600 cs8 -cstopb -parenb -echo -onlcr
while (true) do sudo cat -A /dev/ttys0 ; done
```

---

and let it run. In the other terminal write:

---

```
echo "Hello World!" | sudo tee /dev/ttys0
```

---

I have assumed that `/dev/ttys0` is the device file corresponding to your adapter or cable. Your actual device name could be different. In case of success you will see the same string appear in the first terminal as well.

## 1.9 Temperature Monitors

- USB Temperature and Humidity Monitor with strawberry-linux.
- Directly connected to Analysis PC via USB.
- Readout by a dedicated software “usbrh” on CentOS7.
- One device for each electronics hat (side/top).
- Attached on the Interface board support structure.
- Temperatures have been very stable around 20 degrees Celsius, and humidity are around 52%, with fans on.

## 1.10 Water Level monitor

The USB drive must be formatted with MBR and FAT32.

## 1.11 The WAGASCI rack

TO-DO add picture The WAGASCI rack is located on the south side of the WAGASCI detector as shown in Figure 1.42. It is a single rack where all the acquisition electronics and DAQ PCs are located. In this section I will explain all that there is to know about it and how to turn it on and off. Be aware that until now the Proton module and INGRID module data is not acquired through the WAGASCI rack but through the INGRID one located on the SS floor.

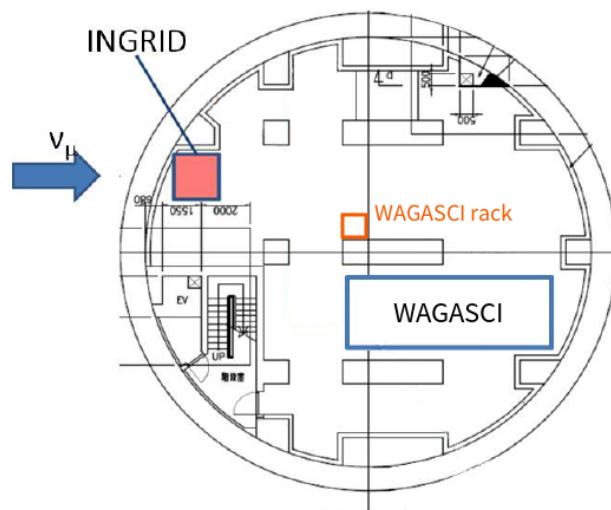


Figure 1.42: The WAGASCI rack location in orange.

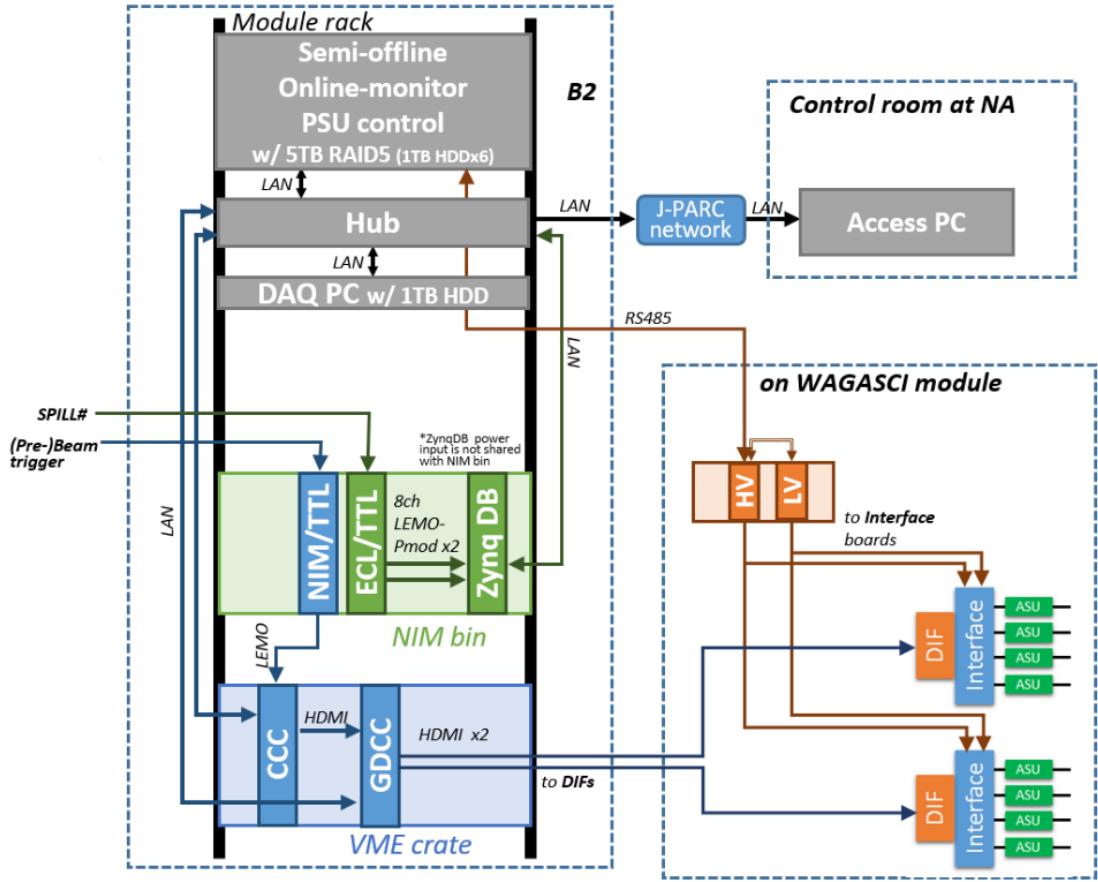


Figure 1.43: The WAGASCI rack schematics

### 1.11.1 NIM crate

### 1.11.2 DAQ PC

### 1.11.3 ANA PC

## 1.12 Beam Trigger and Spill Number

There are two signals coming from the J-PARC neutrino beam line. One is called **Beam Trigger** and is composed of two pulses: the “pre-beam trigger” that comes 100ms before the beam and the “beam trigger” that comes  $30\mu\text{s}$  before the beam. The other signal is called **Spill Number** and, as the name says, it is just the absolute number of each beam spill.. It is a 16-bit digital signal in the ECL logic (see Appendix 2.1.1 for further details on the ECL and other logic families).

These signals are sent from the beam line in the form of optical signals. These optical signals are converted into electric signals in the beam trigger rack, whose location is shown in Figure 1.44 and whose schematics is shown in Figure 1.45. Figure 1.46 shows an overview of the beam trigger and spill number signals processing while Figure 1.47 illustrates the chronograph of all these signal in relation to the neutrino beam.

A spill is just one “shot” of the beam. To ask when the first spill was produced

In addition to the beam trigger signals, the LAN cable coming from the J-PARC LAN network (called also J-LAN) is strung through the beam trigger rack reaching finally the NETGEAR switch on the WAGASCI rack as shown in Figure 1.44.

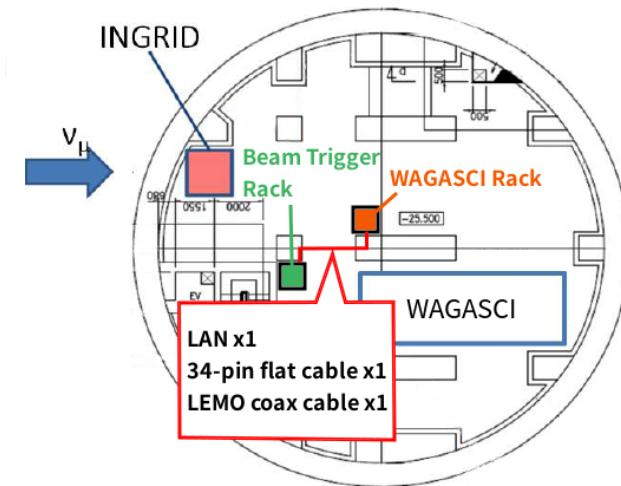


Figure 1.44: Beam trigger rack location on the B2 floor.

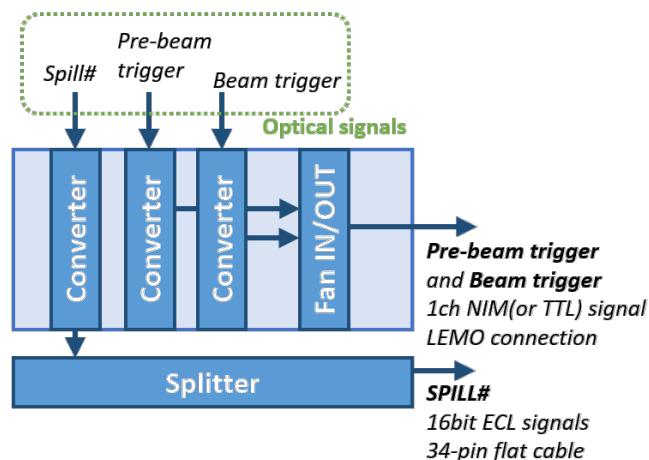


Figure 1.45: Beam trigger rack schematics.

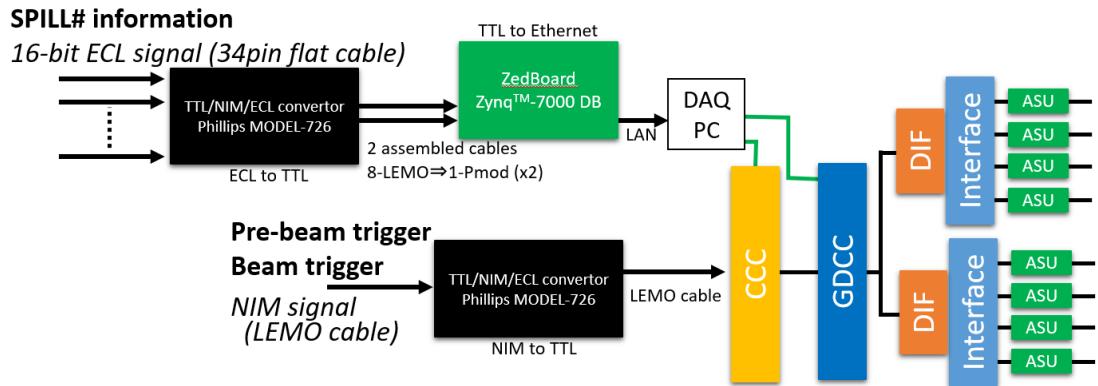


Figure 1.46: Beam trigger processing system overview

#### Beam timing Trigger

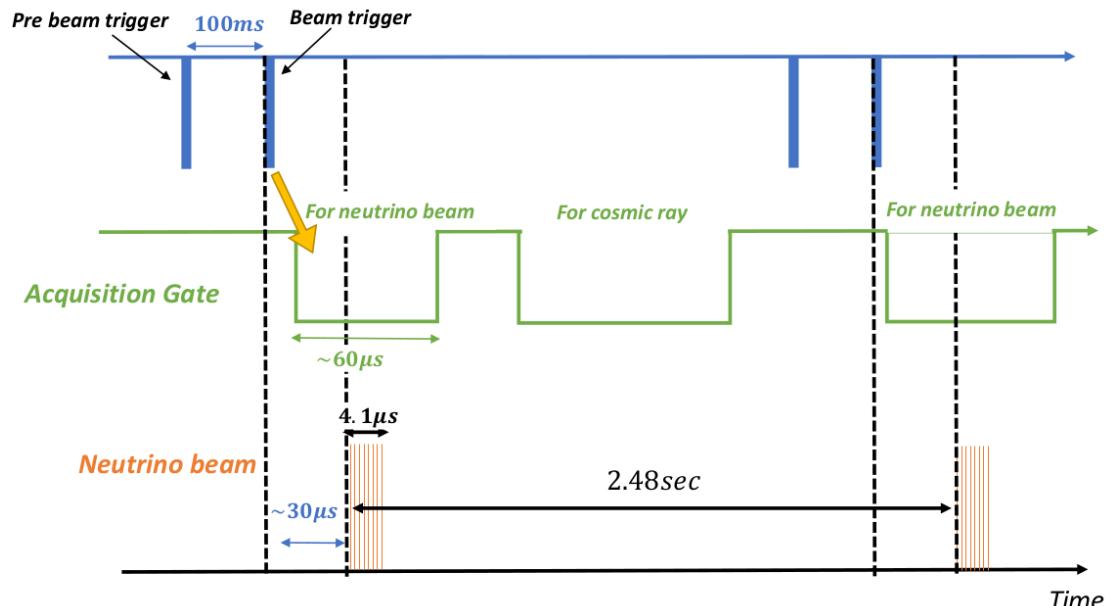
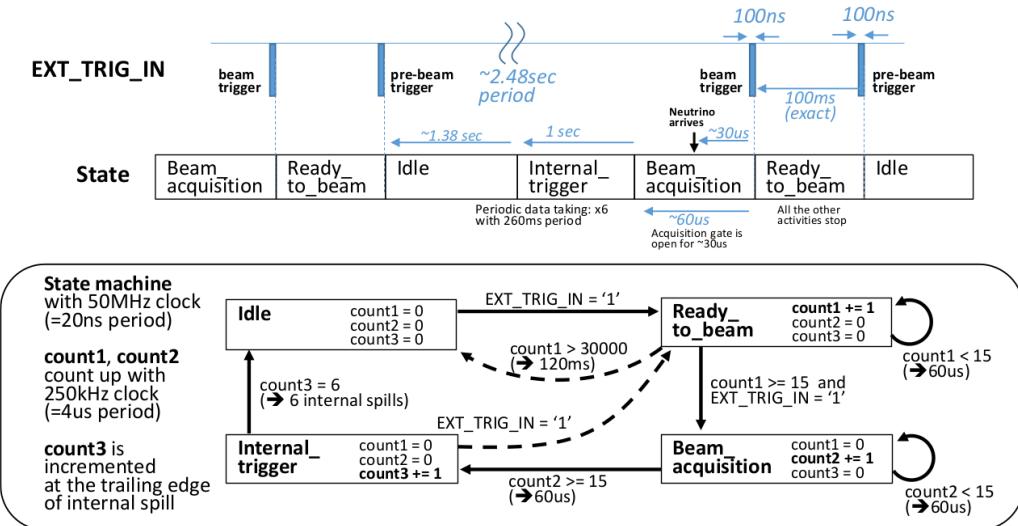


Figure 1.47: Beam trigger chronograph

The Figure 1.48 explains what is the triggering plan for the CCC, i.e. how the CCC manages the Beam Trigger and the Pre-Beam Trigger and generates the beam acquisition signal and internal acquisition signal. Be careful when reading the chronograph because the time is flowing from right to left (consider that in Japan the old way of writing is from right to left that is why sometimes here in Japan you can see graphs with time flowing from right to left).



\*In the case where one of “pre-beam trigger” and “beam trigger” fails to arrive.

→ It may stay at “Ready\_to\_beam”. → The state is back to “Idle” state after 150ms.

\*In the case of “unexpected procedure”(---), error messages would be sent to the DAQ PC via TCP socket.

Figure 1.48: CCC triggering plan

### 1.12.1 Spill Number

The beam spill number is received by optical connection from the neutrino beam. It is converted to ECL electric signal in the Beam Trigger rack and then sent to the WAGASCI DAQ rack, where it is converted to TTL by a “Philips MODEL 726” NIM module and piped to the “ZedBoard Zynq-7000 DB” where it is converted to Ethernet and distributed to the DAQ PC and GDCC.

The CCC is also capable of generating a “internal beam trigger” internally for testing purposes, calibration and measurements on cosmic rays or LEDs. To the internal trigger is associated an “internal spill number”.

There is also a variable called “spill flag” that is generated thanks to the CCC firmware and describes the type of the spill. It is equal to **0x82** if the spill is coming from the neutrino beam. It is equal to **0x92** if the spill is internal. The spill number and spill flag are recorded in the header section of the GDCC Ethernet packages.

To check if this statement is correct.

In the Normal GDCC packet (Section 2.2) used by the ZedBoard to communicate with the GDCC the 2-Bytes **GDCC\_PktID** field is used for the spill number while the 2-Bytes **GDCC\_DataLength** field is used for the spill flag.

### Beam trigger signals from beamline

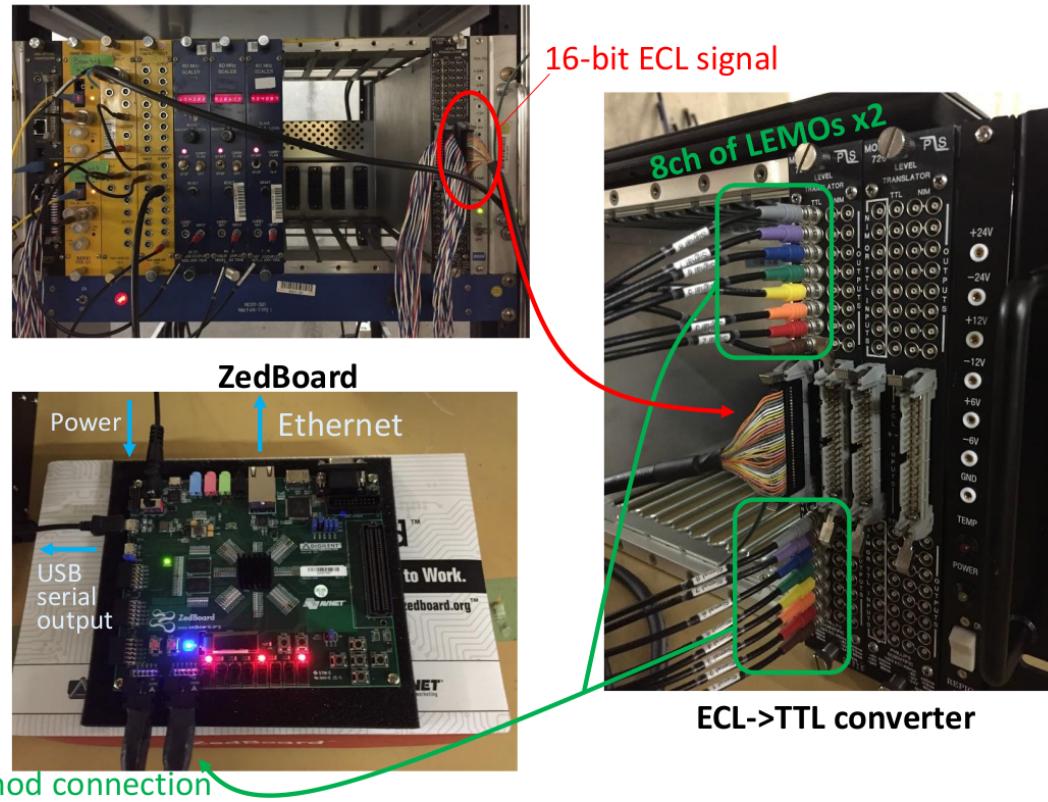


Figure 1.49: Spill number processing boards

<b>Pmod</b>	1	2	3	4	5	6	7	8	9	10	11	12
<b>Hirose 10-pin</b>	1	3	5	7	9	NC	2	4	6	8	10	NC
<b>LEMO</b>	1	2	3	4	GND	NC	7	8	9	10	GND	NC

Table 1.14: Pinout of the Pmod connector on the ZedBoard

# Chapter 2

# Appendix

## 2.1 Logic Levels

Just a review of all the logic families involved in the beam trigger processing. This section may be useful to probe the signals with an oscilloscope.

### 2.1.1 Emitter Coupled Logic (ECL)

Emitter Coupled Logic (ECL), sometimes referred to as Current Mode Logic, is an extremely high-speed digital technology. ECL has a propagation time of 0.5 - 2 ns, which is much faster than TTL. However, its power dissipation is three to 10 times higher than that of TTL.

The output logic of ECL, much like that of TTL, varies from a LOW state to a HIGH state. However, the voltage levels of these states differ between ECL and TTL. The output logic swing of ECL gates varies from a LOW state of -1.75 volts to a HIGH state of -0.9 volts with respect to ground. The following table is an illustration of when positive logic is used while referring to a logic “0” or “1”.

Voltage Level	State	Logic	Boolean
-1.75 V	LOW	False	0
-0.9 V	HIGH	True	1

Table 2.1: Fast command packet format

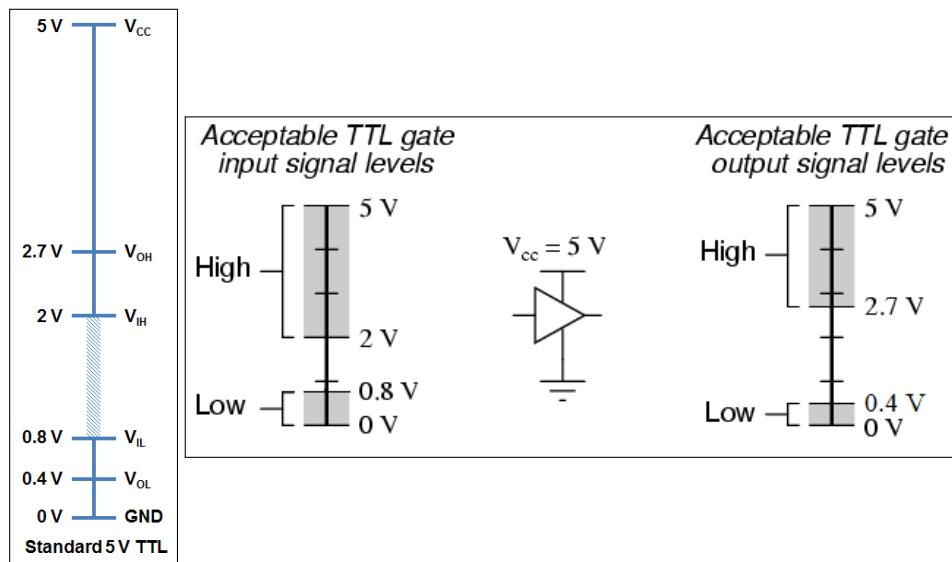
Some common terms used when referring to ECL circuits:

- **V<sub>EE</sub>**: Negative power, which is typically -5.2 volts.
- **V<sub>BB</sub>**: Switching threshold, which is typically -1.29 volts.
- **V<sub>TT</sub>**: Termination voltage, which is typically -2.0 volts.
- **V<sub>CC</sub>**: Ground, on most ECL circuits.

## 2.1.2 Transistor-Transistor Logic (TTL)

Some common terms used when referring to TTL circuits:

- **VOH**: Minimum OUTPUT Voltage level a TTL device will provide for a HIGH signal.
- **VIH**: Minimum INPUT Voltage level to be considered a HIGH.
- **VOL**: Maximum OUTPUT Voltage level a device will provide for a LOW signal.
- **VIL**: Maximum INPUT Voltage level to still be considered a LOW.



You will notice that the minimum output HIGH voltage (VOH) is 2.7 V. Basically, this means that output voltage of the device driving HIGH will always be at least 2.7 V. The minimum input HIGH voltage (VIH) is 2 V, or basically any voltage that is at least 2 V will be read in as a logic 1 (HIGH) to a TTL device. You will also notice that there is cushion of 0.7 V between the output of one device and the input of another. This is sometimes referred to as noise margin.

Likewise, the maximum output LOW voltage (VOL) is 0.4 V. This means that a device trying to send out a logic 0 will always be below 0.4 V. The maximum input LOW voltage (VIL) is 0.8 V. So, any input signal that is below 0.8 V will still be considered a logic 0 (LOW) when read into the device.

What happens if you have a voltage that is in between 0.8 V and 2 V? Well, your guess is as good as mine. Honestly, this range of voltages is undefined and results in an invalid state, often referred to as floating. If an output pin on your device is “floating” in this range, there is no certainty with what the signal will result in. It may bounce arbitrarily between HIGH and LOW.

## 2.1.3 Nuclear Instrumentation Module (NIM)

The NIM standard two types of standards for logical signals, namely:

- Fast-negative logic with rise times of order of 1 ns. The range is set by the current range corresponding to 0V and -8V.

	<b>Output must deliver</b>	<b>Input must accept</b>
Logic 1	-14 mA to -18 mA	-12 mA to -36 mA
Logic 0	-1 mA to +1 mA	-4 mA to +20 mA

Table 2.2: Fast-negative NIM logic

- Slow-positive signals:

	<b>Output must deliver</b>	<b>Input must accept</b>
Logic 1	+4 to +12 V	+3 to +12 V
Logic 0	+1 to -2V	+1.5 to -2 V

Table 2.3: Fast-negative NIM logic

## 2.2 GDCC cheat-sheet

This cheat-sheet is intended for debug only. Normal users (myself included) should not need to care about this. I have included it in the appendix just in case I would need it in future (but I really hope not). The GDCC is built on standard Ethernet. Communication to and from it is done via RAW Ethernet packets:

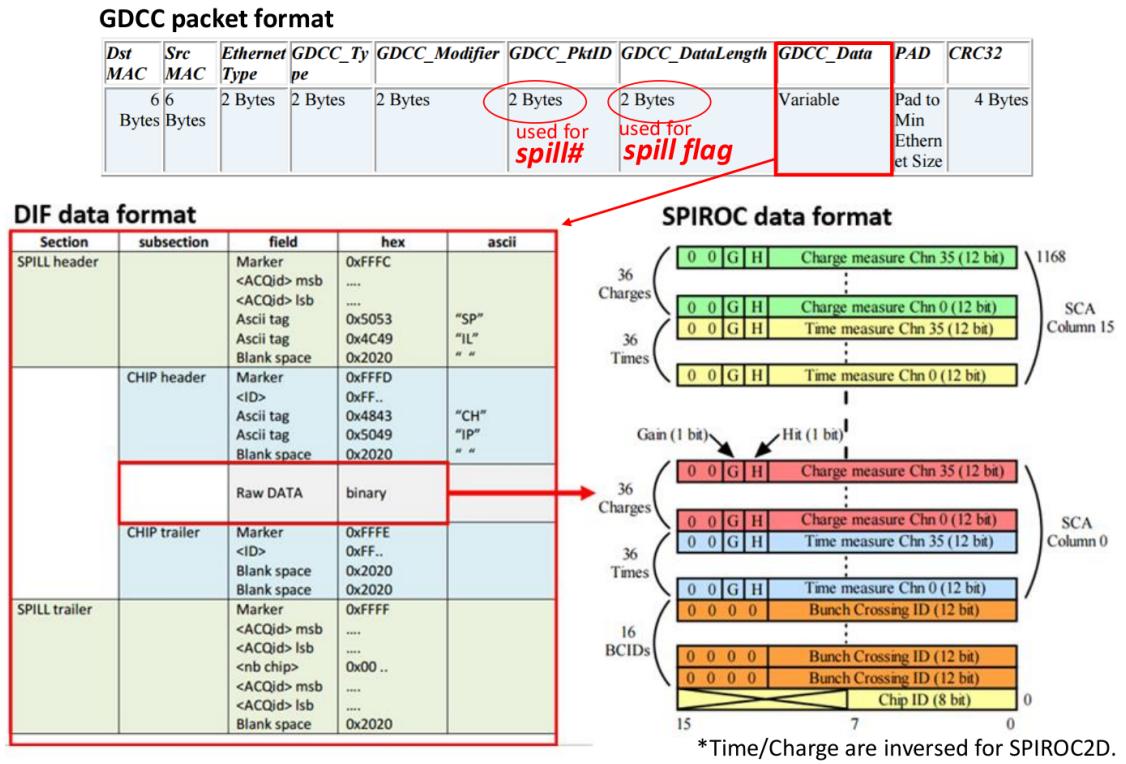


Figure 2.2: Raw packet structure

### 2.2.1 Fast command packet format

Fast commands are generated via two mechanisms. The first is in direct response to various hardware inputs from the CCC into the GDCC and the second is manually via the GDCC → COMPUTER link.

When done via this method the packet used is smaller than the normal GDCC packet format, and is processed separately.

Dst MAC	Src MAC	Ethernet Type	Command_Word	DIF Link	Comma	Data	parity	PAD	CRC32
6 Bytes	6 Bytes	2 bytes	2 Bytes	2 Bytes	1 Byte	1 Byte	2 Bytes	Pad to min Ethernet size	4 bytes

Table 2.4: Fast command packet format

- Ethernet type: set to 0x0809 for Fast Command. These are generally not used in the real world, so we chose them at random. Packets with a different Ethernet Type will be ignored.
- Command word: set to a constant 0xFA57. Future operations may use a different Command\_Word for other usage cases.
- DIF Link: A mask which defines which port the command is for. A value of 0xFFFF would be used as a broadcast to all currently active DIF links.
- Comma: comma character to use

- Data: defines which byte to send as the data byte.
- Parity: is a simple check, the bits of this are defined as follows

Bit	Data Used
0	Lower 8 bits of Command_Word
1	Upper 8 bits of Command_Word
2	Lower 8 bits of DIF_Link
3	Upper 8 bits of DIF_Link
4	Comma
5	Data

We use an Even Parity scheme, and the reason for using this is that the command is recognised almost as soon as the parity is validated, rather than waiting for the full CRC32 to be verified.

### 2.2.2 GDCC packet format

Dst MAC	Src MAC	Ethernet Type	GDCC_type	GDCC_modifier	GDCC_pktID	GDCC_dataLength	GDCC_Data	PAD_CRC32
6 Bytes	6 Bytes	2 bytes	2 Bytes	2 Bytes	2 Byte	2 Byte	Variable Pad to min Ethernet size	4 bytes

Table 2.5: GDCC packet format

- Ethernet type:
  - 0x0810: GDCC data pkt
  - 0x0811: DIF data pkt
- GDCC type: split in 2 bytes (not all are defined)
  - Upper (Sub System Encoding):
    - \* 0x00: GDCC registers (Both directions)
    - \* 0x01: DIF transport (Both directions)
    - \* 0x02: Diagnose memory (Both directions)
    - \* 0xFF: GDCC pkt generator (GDCC →PC)
  - Lower (Operation Encoding):
    - \* 0x00: GDCC PktGenData (GDCC →PC)
    - \* 0x01: Write from PC to GDCC (PC →GDCC)
    - \* 0x02: Read from PC to GDCC (PC →GDCC)
    - \* 0x03: Write ACK (GDCC →PC)
    - \* 0x04: Read reply from GDCC to PC (GDCC →PC)
    - \* 0x05: Read NACK (GDCC →PC)
    - \* 0x08: pkt\_DIF from PC to DIF (PC →DIF)
    - \* 0x09: pkt\_DIF from DIF to PC (DIF →PC)

- \* 0xFF: GDCC Saw Bad Packet (GDCC → PC)

- GDCC modifier: is used to indicate things such as which DIF link a DIF packet should be sent down, that is currently the only use of it. 0xFFFF indicates a broadcast down all DIF links that are currently operational.
- GDCC pktID : This is used to track Replies to things. For example a any GDCC register operations will result in a reply, these replies will have the same PktID in them.
- GDCC data length: is a measure of how many objects there will be in the GDCC Data array. For Register operations on the GDCC it is the total number of GDCC Register Packets that follow. For DIF operations it is the Number of DIF Packets that follow. For DIF Event data it is the Number of Event Packets that follow.
- CRC32: This is not really a user accessible data field. Normally the MAC layer on the Ethernet card will add this, and will strip it on received packets. However, depending on the operation it may or may not be visible and so is included in this definition for completeness. Any packets that fail the CRC32 check on RX at the GDCC will be silently dropped.

### 2.2.3 GDCC Register Packet Format

Access to GDCC registers is done via the following sub packet type.

Address	Data
2 Bytes	4 Bytes

Address is 16 bits, and in general fill all unused data with 0x0 Data is 32 bits, even though most registers are 16. This is to allow future expansion.

Lower bits of data are used first, so a register that returns < 32 bits will return it in the lower bits of the data space, the same for writes.

When performing a Read the packet must still include the space for the data, even though it will be over written by the GDCC internal processing. This just makes things more symmetric for both reads and writes.

You can pack as many register sub packets as you want into an GDCC\_packet. However, they will all be of the same type, eg, all READ or all WRITE, you cannot currently mix them.

### 2.2.4 GDCC DIF Event Packet Format

When Events come into the GDCC from the DIF they are wrapped in an GDCC packet before being sent onward to the COMPUTER. They are dropped verbatim into the GDCC\_Data block of the packet. The GDCC-DIF Link CRC is retained, so that software can check it if needed.

- GDCC\_Type: Will have the upper portion set to DIF Transport and the lower 8 bits set to show which DIF Link it came from.
- GDCC\_PktID: Will be the serial number of the packet, which will increase each time, allowing some way to see if there are missing ones.
- GDCC\_DataLength: Will show the number of encapsulated DIF Packets

Future enhancement might be the addition of a flag to say if the packet from the DIF passed the CRC or not.

### **2.2.5 GDCC Memory Map**

Memory access's to registers inside the GDCC are done using a 16bit address. This address is then subdivided into a Block and Register range. The upper 4 bits define the Block. The lower 12 define the Register.

<b>Block</b>	<b>Address</b>	<b>Register</b>
0x1	0x000	DIF_LINK_TX_EN
	0x002	DIF_LINK_RX_EN
	0x004	DIF_LINK_RTT
	0x006	DIF_LINK_AUTONEG_PAUSE
	0x008	DIF_LINK_RESTART
	0x00A	DIF_LINK_STATUS1
	0x00B	DIF_LINK_STATUS2
	0x00E	DIF_LINK_NO_SIGNAL
	0x010	DIF_LINK_DELAY1
	0x011	DIF_LINK_DELAY2
	0x012	DIF_LINK_DELAY3
	0x013	DIF_LINK_DELAY4
	0x018	DIF_LINK_RTT1
	0x019	DIF_LINK_RTT2
	0x01A	DIF_LINK_RTT3
	0x01B	DIF_LINK_RTT4
	0x020	DIF_LINK_RTT_DONE
	0x022	DIF_LINK_LOCKED
	0x024	DIF_LINK_DCM
0x2		
0x3		
0x4	0x000	GDCC_ENABLES
	0x001	GDCC_TX_MUX_COUNT
	0x006	GDCC_DIF_DATA_MAC_L
	0x007 g	GDCC_DIF_DATA_MAC_M
	0x008	GDCC_DIF_DATA_MAC_H
	0x00E	GDCC_REVISION
	0x00F	GDCC_VERSION
	0x010	GDCC_PKTGEN_CONTROL
	0x011	GDCC_PKTGEN_SIZE
	0x012	GDCC_PKTGEN_COUNT
	0x013	GDCC_PKTGEN_DELAY
	0x014	GDCC_PKTGEN_SEED
	0x015	GDCC_PKTGEN_TXCOUNT
	0x016	GDCC_PKTGEN_MAC_L
	0x017	GDCC_PKTGEN_MAC_M
	0x018	GDCC_PKTGEN_MAC_H

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